

# **AS3956**

# **NFC Forum Compliant Dynamic Tag**

# **General Description**

AS3956 NFC Dynamic Tag IC is the ultimate solution to easily add NFC functionality to electronic devices. Thanks to a high sensitivity ISO14443A frontend and high integrated resonance capacitor, AS3956 offers standalone NFC passive tag functionality in a small footprint. Fast system integration and high speed data transfer are guaranteed by the available SPI and I<sup>2</sup>C interfaces and by the optimized protocols (Tunneling Mode and Extended Mode), allowing bidirectional communication between the device microcontroller and an external NFC compliant device or ISO14443A reader device (PCD).

AS3956 is able to operate fully powered by the RF field, without any external supply. This, combined with an advanced energy harvesting feature, greatly increases battery life time or even allows battery-less designs.

AS3956 is used with an appropriate antenna coil connected to the terminals LC1 and LC2, and behaves as a standard passive ISO 14443A tag (PICC). After the anti-collision protocol stage, based on configuration, AS3956 can operate as a standalone NFC Forum Type 2 Tag or, when tunneling mode is activated, as a bridge between the PCD and the microcontroller, e.g. to emulate a custom or standard ISO14443A Level 3 or Level 4 PICC or a NFC Forum tag. A configurable wake-up signal notifies the microcontroller on ongoing RF activities, in order to minimize overall power consumption.

AS3956 includes an embedded EEPROM memory that can be accessed from the PCD through the RF link or from the microcontroller through the SPI or I<sup>2</sup>C interfaces. Part or all memory can be protected by a 32-bit password, or permanently locked.

AS3956 supports ISO 14443A up to Level 4 and is designed according to EMVCo requirements, to enable the emulation of contactless smart cards or NFC Forum compliant Type 2 or Type 4 Tags.

AS3956 is designed for high reliability, and can operate in a wide power supply range from 1.65V to 5.5V, in a wide temperature range from -40°C to 125°C. EEPROM memory reaches automotive grade quality with endurance of 100000 cycles and data retention of 10 years at 125°C.

Ordering Information and Content Guide appear at end of datasheet.

### **Mandatory Documentation**

Application Note AN02: Dual Interface Data Integrity



# **Key Benefits & Features**

The benefits and features of AS3956, NFC Forum Compliant Dynamic Tag are listed below:

Figure 1: Added Value of Using AS3956

Benefits	Features
NFC Forum compliance for full interoperability	<ul> <li>Type 2 Tag standalone functionality</li> <li>Type 4 Tag emulation with external MCU</li> </ul>
<ul> <li>NFC Forum compliance</li> <li>ISO 14443A compliance up to Level 3 - stand alone</li> <li>ISO 14443A compliance up to Level 4 with ext. micro</li> </ul>	<ul> <li>Operating frequency at 13.56 MHz</li> <li>Bit rate at 106 kbps</li> <li>7-byte UID</li> </ul>
Choice of memory size based on application	• 4 kbit EEPROM (472 bytes of user data)
Allows zero-power standby	Configurable passive wake-up interrupt
Enables long battery life time, or battery-less designs	Energy harvesting to supply up to 5mA (regulated)
Allows fast antenna prototyping (ISO antenna classes 1 to 6)	45 pF integrated resonant capacitor
Design flexibility, easy integration. Fits requirements for various embedded applications	<ul> <li>3/4-wire SPI slave interface up to 5 Mbps</li> <li>I<sup>2</sup>C slave interface up to 1 Mbps</li> </ul>
Design flexibility, easy integration	Programmable I <sup>2</sup> C address
Fits supply requirements for various applications, including industrial	Wide interface supply range (1.65V to 5.5V)
Support for multiple applications, and storage of sensitive data	32-bit password memory protection
High performance and robust data communication, allows custom protocols to be implemented	Tunneling and Extended modes for MCU communication
Consistent NFC behavior of battery supplied devices in e.g. pairing applications	Silent mode (MCU power status detection), configurable between 1.42V and 3.65V
Possibility to disable RF communication	Configurable Chip Kill mode
Small outline, compatibility to common inlay and card manufacturing lines, surface-mount assembly	WL-CSP package     10-pin MLPD 3mm x 3mm package

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# **Applications**

AS3956 is suited to a wide range of applications, including

- NFC connection handover (Bluetooth™, Bluetooth Low Energy, Wi-Fi pairing)
- Equipment setup, service and configuration
- Firmware upgrades
- · Activity and status logging
- Wireless authentication (e.g. access control to buildings and equipment)

### **Typical Markets:**

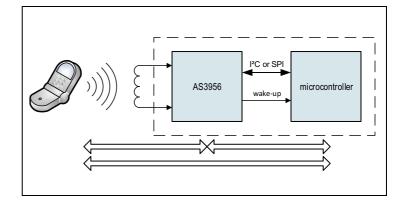
- EMV payment cards
- Consumer electronics, wearables and smart clothing
- Home appliances
- Automotive
- Industrial equipment and building automation
- · Remote sensing
- Gaming

A typical system diagram is depicted in Figure 2.

At the presence of a 13.56 MHz field generated by a NFC device, AS3956 powers up, notifies the microcontroller through a wake-up signal and handles the tag activation sequence. Depending on configuration, several operations are then possible:

- AS3956 exchanges with the NFC device NDEF data stored in the internal EEPROM
- The microcontroller exchanges with the NFC device NDEF data stored in external memory
- The microcontroller exchanges data with AS3956. This
  operation can be performed concurrently with
  communication over the RF link, or also in absence of RF
  power, in presence of an external supply.

Figure 2: Typical System Diagram



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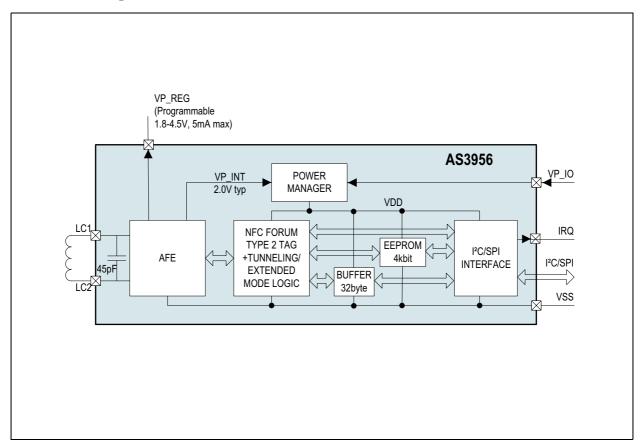
This built-in flexibility makes it ideal for a number of applications requiring non-volatile memory to be accessed when the system is not powered, e.g.:

- personalization data is programmed by the NFC device (even in case SPI / I<sup>2</sup>C is not powered) and it is later read by microcontroller through SPI / I<sup>2</sup>C interface
- Log data is stored periodically by the microcontroller and can then be read by the NFC device even when the microcontroller is not powered
- A NDEF message is regularly modified by the microcontroller (e.g. Bluetooth pin code, or Wi-Fi key, or dynamic URL) and it is later read by a NFC device.

# **Block Diagram**

The functional blocks of this device are shown below:

Figure 3: AS3956 Block Diagram



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AS3956 is composed of NFC-A Analog Front End (AFE), NFC Type 2 Tag Logic, EEPROM, SPI / I<sup>2</sup>C Interface and Power Supply Manager Block (Power Manager).

The AFE is connected to an external tag coil which forms, together with integrated resonant capacitor, a LC tank resonating with the external electromagnetic field frequency of 13.56 MHz. The AFE has built-in rectifier and regulators. The output of the internal regulator (VP\_INT) is used to supply the AFE and also the Logic and EEPROM (through Power Supply Manager). A regulator output VP\_REG is available on a pin to supply external circuitry by harvesting energy from the RF field.

The Power Manager is controlling the power supply of Logic and EEPROM. The two blocks can be supplied either from VP\_ INT or from VP\_IO (SPI / I<sup>2</sup>C power supply) depending on the power mode of the chip. AS3956 offers a power mode where VP\_IO supply is switched to VP\_INT whenever the RF field is present. VP IO is typically used when some activity is started over the SPI / I<sup>2</sup>C and the VP\_INT is too low to be used as a power supply.

The Logic is responsible for handling the anti-collision sequence, when acting as NFC Type 2 Tag, and other data transfer. The interface logic contains also a 32-byte buffer for block transmission between NFC device and AS3956.

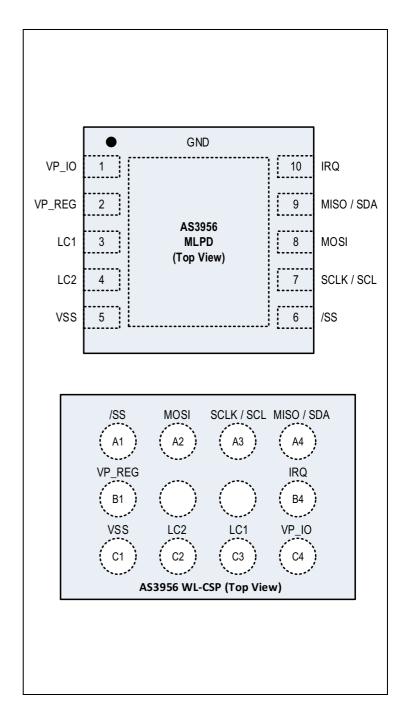
The EEPROM is used to store the UID, configuration and control bits, and user data which can be accessed also via the SPI / I<sup>2</sup>C.

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# **Pin Assignment**

Figure 4: AS3956 Pin Diagram





# **Pin Description**

Figure 5: Pin Description

10-pin MLPD	10-pin WL-CSP	Die	Pin Name	Pin Type	Description
NA	NA	1	meas	Analog I/O	Analog test pin (1)
1	C4	2	VP_IO	Supply Pad	Positive supply of the interface / IC
2	B1	3	VP_REG	Analog Output	Regulator output
3	C3	4	LC1	Analog I/O	Connection to tag coil
4	C2	5	LC2	Analog I/O	Connection to tag coil
5	C1	6	VSS	Supply Pad	Ground, die substrate potential
6	A1	9	/SS	Digital	SPI enable (active low) / I <sup>2</sup> C interface enable
7	А3	10	SCLK / SCL	Input	SPI / I <sup>2</sup> C clock
8	A2	11	MOSI		SPI data input
9	A4	12	MISO / SDA	Digital Output / Tristate	SPI data output / I <sup>2</sup> C data line
10	B4	13	IRQ	Digital Output	Interrupt request output (active high)

# Note(s):

<sup>1.</sup> Pin *meas* is not bonded in MLPD package. It is only used during wafer sort test.



# **Absolute Maximum Ratings**

Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only. Functional operation of the device at these or any other conditions beyond those indicated under Operating Conditions is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Figure 6: Absolute Maximum Ratings

Symbol	Parameter	Min	Max	Unit	Comments
	E	ectrical Pa	arameters		
VDD	DC supply voltage	-0.5	6.5	V	
V <sub>in</sub>	Input pin voltage except LC1 and LC2	-0.5	6.5	V	
	Input pin voltage pins LC1 and LC2	-0.5	6.5	V	
	Peak current induced on pins LC1 and LC2		50	mA	
I <sub>scrLC</sub>	Input current LC1, LC2 (latch-up immunity)	-50	50	mA	JEDEC JESD78D
l <sub>scr</sub>	Input current other pins (latch-up immunity)	-100	100	mA	JEDEC JESD78D
	Ele	ectrostatio	Discharge	ļ	
ESD <sub>HBM</sub>	Electrostatic discharge HBM (all pins except VP_REG)	±2		kV	JEDEC JS-001-2014
ESD <sub>HBMREG</sub>	Electrostatic discharge HBM (VP_REG pin only)	±1		kV	JEDEC JS-001-2014
ESD <sub>CDM</sub>	ESD – charged device models	±5	500	V	JEDEC JESD22-C101F

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Symbol	Parameter	Min	Max	Unit	Comments
	Temperature	Ranges ar	d Storage	Condition	ons
T <sub>strg</sub>	Storage temperature	-55	150	°C	
T <sub>body</sub>	Package body temperature		260	°C	IPC/JEDEC J-STD-020. The reflow peak soldering temperature (body temperature) is specified according IPC/JEDEC J-STD-020 "Moisture/Reflow Sensitivity Classification for Non-hermetic Solid State Surface Mount Devices." The lead finish for Pb-free leaded packages is matte tin (100% Sn).
RH <sub>NC</sub>	Relative humidity non-condensing	5	85	%	
MSL	Moisture sensitivity level for MLPD package	3			Represents a max. floor life time of 168h
IVISE	Moisture sensitivity level for thin WL-CSP	1			Represents an unlimited floor life time

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# **Electrical Characteristics**

All limits are guaranteed. The parameters with min and max values are guaranteed with production tests or SQC (Statistical Quality Control) methods.

# **Operating Conditions**

All in this specification defined tolerances for external components need to be assured over the whole operation conditions range and also over lifetime.

Figure 7: Electrical Characteristics

Symbol	Parameter	Min	Max	Unit	Notes
I <sub>lim</sub>	Limiter current		30	mA	
I <sub>VP_REG</sub>	Output current VP_REG		5.0	mA	
VDD_IO_RF	SPI / I <sup>2</sup> C power supply on VP_IO pin	0	5.5	V	When logic is powered from RF interface without wired interface operational
VDD_IO	SPI / I <sup>2</sup> C power supply on VP_IO pin	1.65 <sup>(1)</sup>	5.5	V	When logic is powered from VP_IO or RF powered with wired interface operational
T <sub>junc</sub>	Junction temperature	-40	125	°C	
VDD_IO_SR	VDD_IO slew rate	15		V/ms	Min. slew rate on VP_IO during power-up for correct operation of wired interface

### Note(s):

1. For VDD\_IO <1.65V correct operation is not guaranteed.

# DC/AC Characteristics for Digital Inputs and Outputs

Figure 8: CMOS Inputs /SS, MOSI and SCLK

Symbol	Parameter	Min	Тур	Max	Unit	Note
V <sub>IH</sub>	High level input voltage	0.75 * VDD_IO			V	
V <sub>IL</sub>	Low level input voltage			0.25 * VDD_IO	V	
I <sub>LEAK</sub>	Input leakage current			10	μΑ	@125°C

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Figure 9: CMOS Outputs MISO and IRQ

Symbol	Parameter	Min	Тур	Max	Unit	Note
VOH	High level output voltage	0.85 * VDD_IO			V	lsource=1mA
VOL	Low level output voltage			0.15 * VDD_IO	V	VP_IO = 5.5V
RO	Output resistance		200	400	Ω	
RPD	Pull-down resistance pad MISO		10		kΩ	See note (1)

### Note(s):

1. Pull down can be enabled while MISO output is in tristate when /SS is high. The activation is controlled by register setting miso\_pd1.

# **Electrical Specifications**

Figure 10: Electrical Specifications (temperature 25°C unless noted otherwise)

Symbol	Parameter	Min	Тур	Max	Unit	Note
I <sub>SB_SPI</sub>	Stand by consumption on VP_IO		<1		μΑ	@ 25°C (RF field not applied) VP_IO=1.8V
V <sub>LIM</sub>	Limiter voltage		5.5	6.0	V	I <sub>LC</sub> =30mA (DC) <sup>(1)</sup>
I <sub>S</sub>	Supply current		450		μΑ	See note (2)
V <sub>HF_PON</sub>	HF_PON threshold (rising VP_INT) power modes 0,3		2.7		V	Rectified RF supply voltage
V <sub>PON_HY</sub>	HF_PON hysteresis		0.5		V	
V <sub>MOD</sub>	Modulator ON voltage drop across LC1 - LC2		1.3 2.6		V	I <sub>LC</sub> =1mA <sup>(1)</sup> I <sub>LC</sub> =30mA <sup>(1)</sup> VP_IO=3.3V
C <sub>RES</sub>	Resonance capacitor		45		pF	

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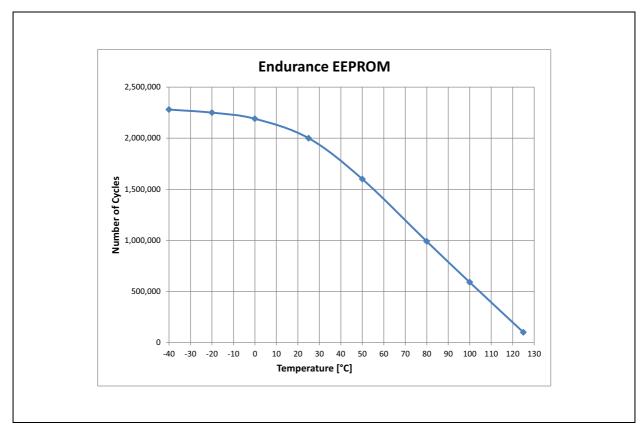


Symbol	Parameter	Min	Тур	Max	Unit	Note
EE <sub>EN</sub>	EEPROM endurance	100 000			cycles	@ 125°C <sup>(3)</sup>
EE <sub>RET</sub>	EEPROM retention	10			years	@ 125°C <sup>(4)</sup>
t <sub>VP_IO_DD</sub>	VP_IO deactivation delay	0.45			ms	

### Note(s):

- 1.  $I_{LC}$  is the current flowing through LC1 and LC2 pins. Exposure to very strong RF fields which produce currents as high as  $I_{LC}$ =30mA for an extended period of time may damage the device.
- 2. Internal supply current measured over VP\_IO pin, by forcing internal digital supply to 2.0V, and applying 13.56 MHz alternative pulses with amplitude 3.0Vpp to LC1 and LC2.
- 3. See Figure 11.
- 4. See Figure 12.

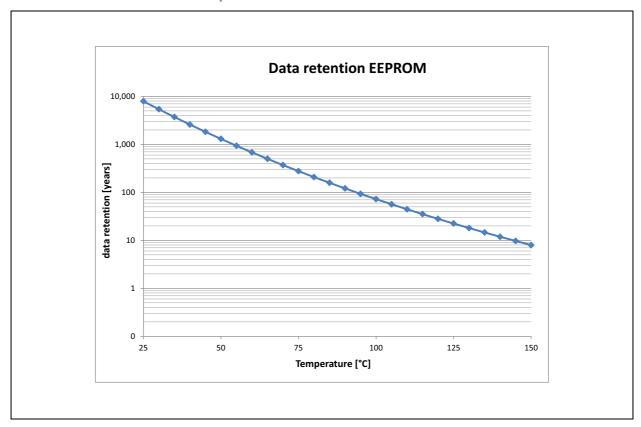
Figure 11: EEPROM Endurance Over Temperature



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Figure 12: EEPROM Data Retention Over Temperature



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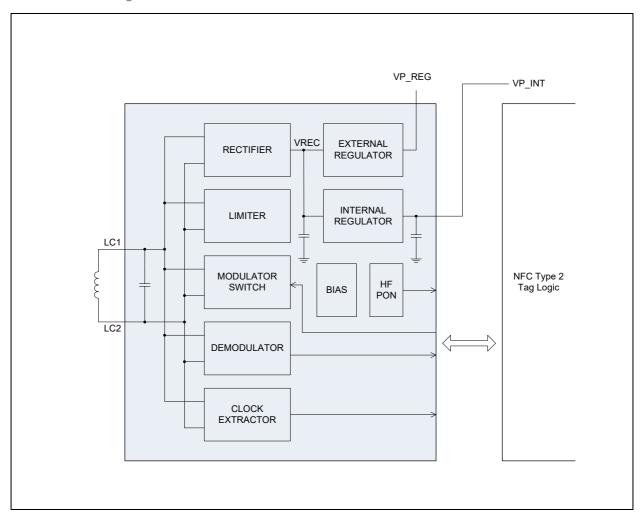


# **Detailed Description**

# Analog Frontend (AFE)

The AFE is connected to external tag coil, which together with the integrated resonant capacitor forms an LC tank resonating at the external electromagnetic field frequency (13.56 MHz). Figure 13 depicts the main AFE building blocks.

Figure 13: PICC AFE Block Diagram



**Rectifier** extracts DC power supply from the AC voltage induced on coil terminals.

**Limiter** limits the maximum voltage on coil terminals to protect AFE from destruction. At voltages that exceed limiter voltage it starts to absorb current (acts as some sort of shunt regulator).

**Modulator Switch** is used for communication the NFC tag to a NFC device. When switched on it will draw current from coil terminals. This mechanism is called load modulation. Variation of current in the modulator switch (ON and OFF state) is seen as modulation by the NFC device.

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**Demodulator** is used for communication NFC device to NFC tag. It detects AM modulation of the NFC device magnetic field. The demodulator is designed to accept modulation according to NFC-A specifications ([NFC Analog] [NFC Digital]).

**Clock Extractor** extracts a digital clock signal from the PCD carrier field frequency which is used as clock signal by logic blocks.

**HF\_PON** enables operation of the AFE and the logic when the supply voltage is sufficiently high. A buffer capacitor and HF\_PON hysteresis guarantee that there is no reset during NFC device modulation.

**Internal Regulator** provides regulated voltage VP\_INT to the AFE and in most cases also to EEPROM and logic blocks. A buffer capacitor is also integrated.

**External Regulator** provides regulated voltage on external pin VP\_REG where it can be used to supply some external circuitry. The regulated voltage and output resistance can be adjusted using EEPROM settings. Appropriate external buffer capacitor is needed in case VP\_REG is used in the application. Current which may be provided depends on reader field strength, antenna size and Q factor, but it is limited to I<sub>VP\_REG</sub> maximum.

**Bias** provides bias currents and reference voltages to AFE analog blocks.

### **Power Management**

AS3956 power management comprises of four different modes to fit requirements of different applications. AS3956 supports two power sources, whose activation depends on the selected power mode. Where an external supply is connected to VP\_IO, the slew rate during power-up must be VDD\_IO\_SR minimum or greater to ensure correct operation.

### Power Mode 0 - Default Power Mode

In this power mode, the Power Manager is controlling the supply of the PICC Logic, EEPROM and SPI / I<sup>2</sup>C Interface (VDD). Its inputs are VP\_INT (rectified and regulated supply extracted from RF field) and the VP\_IO (supplied by external battery).

In standby mode, when AS3956 is not in the RF field (the condition is that rectified supply voltage is below HF\_PON threshold) and the SPI /  $I^2C$  is not active (/SS is high), the VDD supply is disconnected. The only current consumption in this state is leakage on VP\_IO, mainly due to level shifters and SPI /  $I^2C$  pins.

When AS3956 is placed in a RF field, VDD is connected to VP\_INT. This happens once the HF\_PON threshold is exceeded.

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VP\_IO is connected to VDD only when AS3956 is not in the RF field (rectified supply voltage is below HF\_PON threshold) and the SPI / I²C interface is activated by pulling /SS signal low. The switch to VP\_IO is controlled by /SS signal. The VP\_IO deactivation is delayed by  $T_{VP\_IO\_DD}$ , so that the switch shall stay closed in case of shorter times between successive SPI / I²C activations. The switch is also closed during EEPROM writes activated over SPI / I²C.

At activation of the switch, the time between the falling edge of the /SS signal and rising edge of SCLK shall be at least  $T_{NCSL}$  minimum to allow charging of internal VDD buffer capacitor, expiration of POR signal and to perform a complete IC initialization. Please note that the only SPI /  $I^2C$  operations, which are allowed in this mode, are read and write of EEPROM and registers.

If the RF field is lost during operation and the external system (MCU) is supplied over battery and /SS is low then power manager will automatically connect the VDD to VP\_IO.

To enable low power mode where tag consumes I<sub>SB\_SPI</sub>, the following conditions must be met:

- SPI interface configured
- All SPI interface input lines (including /SS) must be set to high
- All SPI output lines must be open

# Power Mode 3- External Supply Used to Power EEPROM and Logic

In this case the external supply shall be used to provide power to digital blocks, EEPROM, SPI / I<sup>2</sup>C pads and MCU. External supply VP\_REG is not used. Since this mode can be enabled only after initialization of the chip, the /SS line must be either permanently set to low or pulled low for short time to complete the initialization. When reading from or writing to the EEPROM via I<sup>2</sup>C/SPI it is recommended that the MCU should first check whether there is enough energy available, then switch to Power mode 3 and execute the SPI/I<sup>2</sup>C read or write and finally switch back to the original power mode if required.

In this mode, the HF\_PON threshold of the chip is set so that it will operate at  $V_{\rm HF\_PON.}$ 

If this mode is enabled, AS3956 will not be turned off as long as there is an external power present.

Power Mode 3 requires external power to be provided on VP\_IO. It is therefore very important to always power up in Power Mode 0 or 1 (power mode set to PM 0 or 1 in EEPROM) and then switch to Power Mode 3 by SPI/ I²C command only when external power is available by writing to IC Configuration Register 2. Before disconnecting external power i.e. switching off VP\_IO, it is recommended to switch the chip back into Power Mode 0 again by writing to IC Configuration Register 2.

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### Chip Initialization in the Different Power Modes

During chip initialization, values from the EEPROM configuration bytes are loaded into the configuration registers.

Figure 14: **Chip Initialization in the Different Power Modes** 

Power Mode	Chip Initialization Occurs When			
0	RF field or external power VP_IO turns on and /SS is low, whichever first.			
3	Power up in PM 0 or 1 first and then switch to PM 3 by command from external microcontroller when external power is available			

### Resetting the AS3956

To fully reset the AS3956 it is necessary to remove all sources of power:

- · Turn off the RF field and
- Take /SS pin high **or** remove power from the VP\_IO line.

### **Interface Arbitration**

Concurrent access to AS3956 internal EEPROM from RF or SPI / I<sup>2</sup>C requires arbitration, to resolve conflicts or undesired behaviour.

# Arbitration Mode 0 (first-come-first-serve)

AS3956 arbitrates EEPROM read/write accesses according to first-come-first-serve principle.

- In case no read/write access is currently ongoing, both RF and SPI / I<sup>2</sup>C interfaces are allowed to read/write into EEPROM.
- In case a read/write request comes over RF, while SPI / I<sup>2</sup>C is reading/writing, AS3956 will return a NAK\_5 and will then enter SENSE/SLEEP state. The chip will generate an I init IRQ and an EEPROM access error IRQ.
- In case a read/write request comes over SPI / I<sup>2</sup>C while RF is reading/writing, AS3956 will trigger a l\_err\_acc interrupt (see Figure 94).
- In case a read request comes over SPI / I<sup>2</sup>C while RF is reading/writing to the EEPROM, the AS3956 will reply all zeros over SPI / I2C.

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# **Energy Harvesting**

AS3956 has energy harvesting capability. The regulated voltage output pin for energy harvesting is VP\_REG. The energy harvesting is enabled only in Power Mode 0. Figure 16 shows settings of the regulated voltage output. The AS3956 can supply I<sub>VP\_REG</sub> from VP\_REG in a strong field. The current which can be supplied by VP\_REG and its output resistance will vary with field strength, antenna class and voltage setting. The output voltage and resistance can be set by Configuration Byte IC\_CFG1. The energy harvesting can be disabled by setting the output resistance register to 0 as shown in Figure 15.

Figure 15:
Output Resistance Settings

rreg<1:0>	Typ. Output Resistance [Ω]	Comment
00b	X	Disabled – output pin is in tristate
01b	100	
10b	50	
11b	25	

Figure 16: Regulated Voltage Output Settings

vreg<4:0>	Typ. Output Voltage [V]
00000	1.9
00001	2.0
00010	2.1
00011	2.2
00100	2.3
00101	2.4
00110	2.5
00111	2.6
01000	2.7
01001	2.8
01010	2.9
01011	3.0

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vreg<4:0>	Typ. Output Voltage [V]				
01100	3.1				
01101	3.2				
01110	3.3				
01111	3.4				
10000	3.5				
10001	3.6				
10010	3.7				
10011	3.8				
10100	3.9				
10101	4.0				
10110	4.1				
10111	4.2				
11000	4.3				
11001	4.4				
11010	4.5				
11011	1.8				
11100	1.8				
11101	1.8				
11110	1.8				
11111	1.8				

### Note(s):

1. The regulated output voltage setting at 1.8V is measured with min. antenna voltage of  $V_{LC2-LC1}=3.6V$  DC and the regulated voltage setting at 4.5V is measured with a min. antenna voltage of  $V_{LC2-LC1}=5.5V$  DC. Abs. accuracy at 25°C is  $\pm 150$ mV at 1.8V linearly increasing to  $\pm 225$ mV at 4.5V, step size is 100mV  $\pm 20$ mV.

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#### Silent Mode

Silent mode enables detection of the power status of a circuit whose supply (Vdd) is connected to VP\_IO pin. If this mode is enabled and the voltage measured on pin VP\_IO is below the configured threshold value, the RF part of AS3956 will be disabled, and the IC will not be responsive to incoming commands. Silent mode settings can be performed by using Configuration Byte IC\_CFGO.

This feature overcomes a potentially inconsistent behavior in a battery powered system, where a passive NFC tag can always communicate with a NFC device, also in case the battery is not sufficiently charged to supply the rest of the system. A typical example is when the NFC tag is used for Bluetooth pairing: AS3956 would trigger a pairing procedure only in case the system is fully operational by monitoring the supply voltage.

# **Memory Protection**

AS3956 internal memory can be protected from unauthorized access by enabling password authentication. A 32-bit password can be set to protect the full user memory, or part of it, to allow the creation of a public data and a private data area. Password protection can be applied for read and write accesses.

Password authentication is performed through a standard WRITE command to the Authentication Password block. A maximum of 7 negative attempts are permitted before the chip is locked. Once authenticated, the user can modify the password.

Password protection applies to RF communication only.

Further information on how to handle password authentication can be found in Authentication Password, Configuration Byte AUTH\_CFG, Configuration Byte AUTH\_CNT and Configuration Byte AUTH\_LIM.

### Passive Wake-Up

AS3956 is able to operate NFC tag operations standalone and fully powered by the RF field. The connected MCU can remain in standby/sleep mode as long as its intervention is not required by the application, in order to save power. AS3956 can be configured to notify the MCU through a wake-up interrupt.

A number of triggering events can be selected, e.g.:

- · Power up
- SELECTED state entered
- Reception of SLP\_REQ command
- NFC device has updated memory content

For a complete interrupt source list, please refer to the section Interrupt Registers.

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# **Chip Kill**

Some applications require that the RF link is active only under certain conditions, e.g. during device configuration only in a controlled environment like a production facility.

AS3956 can be configured by the MCU in order to restrict the NFC device access to the system. By setting the Configuration Byte CHIP\_KILL in EEPROM, the MCU can disable access to SPI / I<sup>2</sup>C from the RF link (i.e. Tunneling and Extended mode are permanently disabled), or even disable RF communication completely. In the latter case, AS3956 will not respond to incoming RF commands.

This configuration can be modified only by the MCU through  $SPI/I^2C$  interfaces.

# **NFC Tag Functionality**

### **Communication Principle**

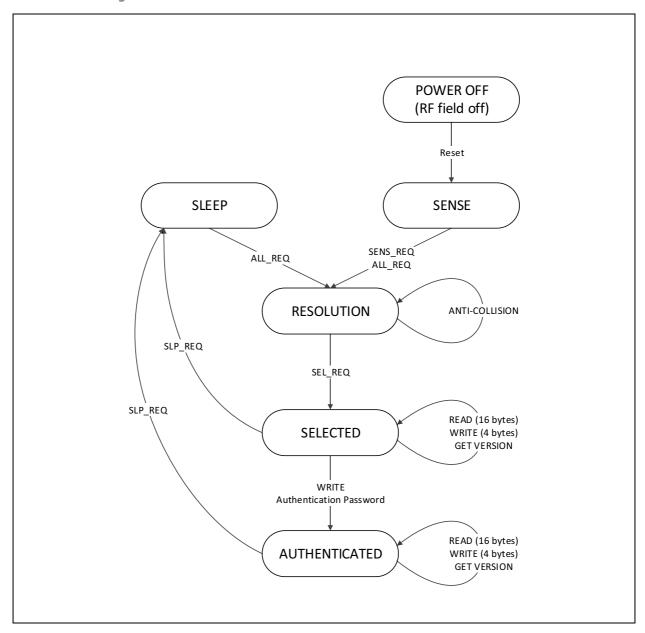
AS3956 autonomously executes complete NFC-A anti-collision communication sequence, during which the 7-byte UID is used ([NFC Analog] [NFC Digital]). After anti-collision, the NFC tag is brought into SELECTED state where read and write commands can be processed. The NFC tag will accept only read and write command issued to the address space actually available in AS3956 EEPROM. Any attempt to access an address outside the internal memory address space will be rejected. This default behavior of the NFC tag can be modified by enabling Tunneling or Extended mode.

A simplified AS3956 state diagram is shown in Figure 17.

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Figure 17: AS3956 State Diagram



### **SENSE State**

After a power-on reset (POR), AS3956 switches to the SENSE state. This state is exited when a SENS\_REQ or an ALL\_REQ command is received from the NFC device. Any other data received while in this state is interpreted as an error and AS3956 remains in SENSE state.

When in SELECTED or AUTHENTICATED state, a correctly executed SLP\_REQ command will modify the default waiting state from SENSE to SLEEP state. SLEEP state can be exited when an ALL\_REQ command is received.

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#### **SLEEP State**

Together with SENSE state, SLEEP state is the other waiting state for AS3956. SLEEP state can be entered upon reception of a SLP\_REQ command. The distinction between SENSE and SLEEP state is made necessary to discriminate selected and not yet selected tags.

AS3956 can only exit this state upon reception of an ALL\_REQ command. Any other command received in this state is interpreted as an error and AS3956 state remains unchanged.

#### **RESOLUTION State**

In RESOLUTION state, the NFC device is resolving the tag UID. Since AS3956 has a double size UID, the RESOLUTION state actually comprises of two sub-states, where the anti-collision procedure is carried out in Cascade Level 1 and 2. Please refer to [ISO18092] for further information.

#### **SELECTED State**

All memory operations are operated in SELECTED state.

Upon reception of a SLP\_REQ command, SELECTED state is exited and AS3956 transits to SLEEP state. Any other command received when the device is in this state is interpreted as an error. Depending on its previous state, AS3956 returns to either SENSE or SLEEP state.

Upon reception of a SECTOR SELECT command, AS3956 returns a NAK and transits to SENSE or SLEEP state, depending on its previous state.

AS3956 transits to the AUTHENTICATED state after successful password verification, using a standard WRITE command to a dedicated memory address (see Authentication Password). The number of permitted failed authentications is set to 7, after which AS3956 transits to LOCKED sub-state (not shown in the picture). When LOCKED state is entered, only the MCU can bring AS3956 back to SENSE state by resetting the authentication counter (Configuration Byte AUTH\_CNT) back to 0 and issue a Set Default, or Go To Sense, or Go To Sleep command.

When in LOCKED sub-state, all memory operations are only allowed in the memory area not password protected, as defined by the configuration byte Configuration Byte AUTH\_LIM.

Upon reception of a SLP\_REQ command, SELECTED state is exited and AS3956 transits to SLEEP state.

Any other command received when the device is in this state is interpreted as an error and, depending on its previous state, AS3956 returns to either SENSE or SLEEP state.

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### **AUTHENTICATED State**

In this state, all operations on memory blocks, which are configured as password verification protected, can be performed.

Upon reception of a SECTOR SELECT command, AS3956 returns a NAK and transits to SENSE or SLEEP state, depending on its previous state.

Upon reception of a SLP\_REQ command, AUTHENTICATED state is exited and AS3956 transits to SLEEP state.

Any other command received when the device is in this state is interpreted as an error and, depending on its previous state, AS3956 returns to either SENSE state or SLEEP state.

# NFC Forum Type 2 Tag Support

NFC Forum NFC-A commands ALL\_REQ, SENS\_REQ, SDD\_REQ, SEL\_REQ, SLP\_REQ are required for anti-collision. Commands READ and WRITE are used for internal memory access. If NFC device issues a SECTOR SELECT command, AS3956 shall always reply with NAK.

Figure 18: NFC-A vs ISO14443 Terminology

NFC-A Term	ISO14443 Term							
States								
SENSE	IDLE							
SLEEP	HALT							
RESOLUTION	READY							
SELECTED	ACTIVE							
Commands /	Responses							
SENS_REQ	REQA							
ALL_REQ	WUPA							
SENS_RES	ATQA							
SSD_REQ	AC							
SEL_REQ	SELECT							
SLP_REQ	HLTA							

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# **UID** Coding

Anti-collision procedure is based on the Unique Identification Number (UID). AS3956 supports double size UID (7 bytes). First three bytes of the UID are hardwired inputs to the PICC Logic (uid<23:0>). The last 4 bytes of the UID are stored in EEPROM UID block.

# First UID Byte (uid0)

The first byte of UID is Manufacturer ID according to [ISO7816-6]. It is coded on bits *uid*<7:0>. **ams** IC Manufacturer ID is 3Fh.

## Second UID Byte (uid1)

The second byte of UID (uid<15:8>) is reserved for **ams**' chip type (IC Type). Every **ams**' RFID tag IC has its own chip type assigned. AS3956 IC type is 14h.

### Third UID Byte (uid2)

The third byte of UID (uid<23:16>) is set to 02h.

### Figure 19:

**Coding of First Three UID Bytes** 

UID Byte	Value (Hex)
uid0	3F
uid1	14
uid2	02

# Last Four UID Bytes (uid3-uid6)

The last 4 bytes of UID are read from EEPROM (UID block) and pre-programmed during IC production. Those 4 bytes are unique, and cannot be modified.

Figure 20:

**Last Four UID Bytes** 

UID Byte	UID Block Bits			
uid3	b7-b0			
uid4	b15-b8			
uid5	b23-b16			
uid6	b31-b24			

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### Coding of SENS\_RES, SEL\_REQ, ACK and NACK

Several bits in certain responses are defined as don't-care in the NFC-A standard [NFC Digital], some others are defined by optional choices in standard protocol. This chapter defines how these bits are actually set in AS3956.

### SENS\_RES Response

SENS\_RES is a response on ALL\_REQ and SENS\_REQ commands. The SENS\_RES is defined by Configuration Bytes SENSR1 and SENSR2 stored in EEPROM.

Figure 21:
Coding of SENS RES Response

b15	b14	b13	b12	b11	b10	b9	b8	b7	b6	b5	b4	b3	b2	b1	b0
	SENSR2										SEN	SR1			

# SEL\_RES Response, Cascade Level 1 and 2

SEL\_RES is the response to SEL\_REQ command. Since AS3956 UID is double sized, SEL\_RES responses for Cascade Level 1 and Cascade Level 2 are defined. SEL\_RES on Cascade Level 1 and 2 is defined with Configuration Byte SELR except for cascade bit 3. The response on Cascade Level 2 is also configured by *selr\_b6\_inv* bit which, when set, inverts cascade bit 6 in SEL\_RES response on Cascade Level 2 (see IC\_CFG2).

Figure 22: SEL\_RES CL1 Coding

b8 MSB	b7	b6	b5	b4	b3	b2	b1 LSB	Description
	se	el_res<7:3	3>		1	sel_re	s<1:0>	Cascade bit set: UID not complete

Figure 23: SEL\_RES CL2 Coding

b8 MSB	b7	b6	b5	b4	b3	b2	b1 LSB	Description
sel_res<7:6>		sel_res<5>	sel_res<4:3>		0	sel_res<1:0>		selr_b6_inv set to 0
		NOT sel_res<5>			O			selr_b6_inv set to 1

#### Note(s):

1. According to [ISO14443-3], all bits except b3 are "don't care" for Cascade Level 1, and all bits except b6 and b3 are "don't care" for Cascade Level 2. Bit b6 in CL2 indicates whether the tag is compliant to [ISO14443] or not (resp. b6=1 and b6=0). In case of applications requiring EMVCo compliance, bit b6 in Cascade Level 1 shall be set as bit b6 in Cascade Level 2 ([EMVCO-1]).

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# **ACK Response**

The ACK response of AS3956 is a 4-bit value Ah.

# **NACK Response**

The AS3956 uses all four combinations of NAK values. The usage of various NAK values is explained in section Error Handling.

# Access to UID, SENS\_RES and SEL\_REQ During Anti-Collision

UID block, SENSR1, SENSR2 and SELR bytes are stored in the 32 byte buffer. The purpose of storing these data into the buffer is faster access to the data and UID verification during the anti-collision procedure. Buffer access over SPI / I<sup>2</sup>C is locked until NFC tag enters SELECTED state.

### **Get Version Command**

In addition to standard NFC tag commands, AS3956 supports a custom Get Version command. This command consists of 8 bits and shall be transmitted only in standalone and Extended mode when the tag is SELECTED state. The command code and the tag response are shown resp. in Figure 24 and Figure 25.

Figure 24: Coding of Get Version Command

b8	b7	b6	b5	b4	b3	b2	b1
0	1	1	0	0	0	0	0

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Figure 25: Response to Get Version Command

Byte No.	Descr	Comment	
0	Fixed Header	00h	
1	Vendor Id	3Fh	ams AG
2	Product Type	14h	AS395x
3	Product Subtype	duct Subtype 02h	
4	Major Product Version	01h	1
5	Minor Product Version	00h	V0
6	Storage Size	17h	See note (1)
7	Supported Features	01h or 02h	See note (2)

### Note(s):

- 1. The most significant 7 bits of the storage size byte are interpreted as an unsigned integer value *n*. As a result, it codes the total available user memory size as 2<sup>n</sup>. If the least significant bit is 0b, the user memory size is exactly 2<sup>n</sup>. If the least significant bit is 1b, the user memory size is between 2<sup>n</sup> and 2<sup>n+1</sup>.
  - The user memory is the memory available for user data (Capability Container and lock bits are excluded)
- 2. The figure below is maintained consistently across the whole AS395x family, where Get Version command is supported.

Figure 26: Get Version Response, Byte 7

	Get Version							
Byte No. 7	Description							
b7								
b6	00000b: ISO14443A Level 3 supported, max baudrate 106 kbps, Tunneling and							
b5	Extended mode present, Password protection available, energy							
b4	harvesting available Others: RFU							
b3								
b2	000b: No wired interface available							
b1	001b: SPI slave, passive wake-up available 010b: I <sup>2</sup> C slave, passive wake-up available							
b0	o rob. i C siave, passive wake-up available							

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# **Memory Organization**

AS3956 contains an embedded EEPROM module which can be accessed via RF or SPI /  $I^2$ C interface. EEPROM contains 4096 bits (512 bytes) organized in 128 blocks of 4 bytes each. Blocks in EEPROM are numbered from 00h to 7Fh. Bits in a block are numbered from 0 to 31.

Most of the EEPROM is NFC Type 2 Tag user data area (472 bytes). The position of the dynamic lock bits is fixed at the end of NFC Type 2 Tag user data area (blocks 7Ah and 7Bh). The configuration bits which define AS3956 operating options are stored in blocks 01h, 7Ch, 7Dh, 7Eh, 7Fh. Housekeeping information is stored in block 00h. 4kbit EEPROM organization is shown in Figure 27.

# **4kbit EEPROM Organization**

Numbers of dynamic lock bits:

- Data area size in bytes:
   4\*(127 3) 7 17 = 472 bytes
- Number of dynamic lock bits: (472 48) / 8 = 53 bits (53 bits)

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Figure 27: 4kbit EEPROM Organization

	Byte Number in Block										
Block	0	1	2	3	Description	Access					
00h	UID0	UID1	UID2	UID3	UID / Internal	RO					
01h	FAB_CFG0	FAB_CFG1	FAB_CFG2	FAB_CFG3	Fabrication data	RO					
02h	Internal 8	Internal 9	Lock 0	Lock 1	Internal / Lock	ОТР					
03h	CC 0	CC 1	CC 2	CC 3	CC	ОТР					
04h	Data 0	Data 1	Data 2	Data 3	Data	RW					
05h	Data 4	Data 5	Data 6	Data 7	Data	RW					
06h	Data 8	Data 9	Data 10	Data 11	Data	RW					
07h : : 79h					Data	RW					
7Ah	Lock 2	Lock 3	Lock 4	Lock 5	Lock	ОТР					
7Bh	Lock 6	Lock 7	Lock 8 <sup>(1)</sup>	Reserved 0	Lock / Reserved	ОТР					
7Ch	RFP0	RFP1	RFP2	RFP3	Authentication password	RW					
7Dh	CHIP_KILL	AUTH_CNT	AUTH_LIM	AUTH_CFG	Authentication settings	RW					
7Eh	SENSR1	SENSR2	SELR	IC_CFG0	Config. block 0	RW					
7Fh	IC_CFG1	IC_CFG2	MIRQ_0	MIRQ_1	Config. block 1	RW					

### Note(s):

1. Bits that are not used should be set to 0.

Access properties:

RO: Read only, writing to this word is not possible

RW: Reading and writing to this word is possible

OTP: One time programmable. A bit of this word once set to 1 cannot be set back to 0.

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# **UID Bytes**

The UID block contains four LSB bytes of the 7-byte UID which is used during anti-collision and selection process. Every IC is programmed by a unique number during fabrication process at ams. See UID Coding about details on UID.

This block stores some IC manufacturer data which is programmed and locked during fabrication process at ams.

UID is treated as IC internal configuration, and is permanently locked during IC production.

# **Fabrication Data**

Fabrication data are used to set internal configuration and trimming values. They are treated as IC internal configuration.

Fabrication Data FAB\_CFG0

Figure 28: Fabrication Data FAB\_CFG0

Conf. Bit	Name	Default	Function	Note
b7	NA	0		In AS3955 this was an EEPROM 2kbit option
b6	i2c	0	1: SPI interface is changed to I <sup>2</sup> C	
b5	slnt<2>	0	Trim bit for silent mode	
b4	slnt<1>	0	Trim bit for silent mode	
b3	sInt<0>	0	Trim bit for silent mode	
b2	rffot<2>	0	Trim bit for VP_REG	
b1	rffot<1>	0	Trim bit for VP_REG	
b0	rffot<0>	0	Trim bit for VP_REG	

### Note(s):

1. This byte can be set only during the production in a test mode.

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### Fabrication Data FAB\_CFG1

Figure 29: Fabrication Data FAB\_CFG1

Conf. Bit	Name	Default	Function	Note
b7	fdel<3>	0		
b6	fdel<2>	0	PCD to PICC frame delay time compensation;	
b5	fdel<1>	0	frame compensation defined as fdel*1/fc	
b4	fdel<0>	0		
b3	osct<1>	0	Oscillator trimming bits	
b2	osct<0>	0	Oscillator triffilling bits	
b1	decc<1>	0	Decoder compensation register	
b0	decc<0>	0	Decoder compensation register	

### Note(s):

1. This byte can be set only during production.

The *fdel* bits define frame delay time (FDT) adjustment and represent a time compensation in number of clocks of carrier frequency. The *osct* bits are trimming bits for the internal oscillator.

Fabrication Data FAB\_CFG2

Figure 30: Fabrication Data FAB\_CFG2

Conf. Bit	Name	Default	Function	Note
b7	test_mode	0	0: Test mode is disabled	
b6	mod_r	0	1: The modulator switch resistance is decreased	
b5	i2c_pu	0	1: Enable pull-ups for SDA and SCL when I <sup>2</sup> C is used	
b4	miso_pd1	0	1: Pull down on MISO when \SS is high	
b3	NA	0	Do not change from default	
b2	rfu	0	Reserved for future use	
b1	rfu	0	Reserved for future use	
b0	rfu	0	Reserved for future use	

### Note(s):

1. This byte can be set only during the production in a chip test mode.

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#### Fabrication Data FAB CFG3

Figure 31: **Fabrication Data FAB\_CFG3** 

Conf. Bit	Name	Default	Function	Note
b7	uid_crc<7>			
b6	uid_crc<6>			
b5	uid_crc<5>			
b4	uid_crc<4>		CRC value calculated on UID	
b3	uid_crc<3>		Che value calculated off OID	
b2	uid_crc<2>			
b1	uid_crc<1>			
b0	uid_crc<0>			

#### Note(s):

1. This byte can be set only during production.

# **Reserved Bytes**

The reserved bytes belong to reserved memory areas.

### **OTP Blocks**

Write and Read Lock blocks are OTP (One Time Programmable). This means that once they are set to 1, they cannot be set back to 0. Since setting OTP bits is an irreversible operation, it is strongly recommended to perform this operation in controlled environment.

### **Lock Bits**

The bits of byte 2 and 3 of block 02h represent the field-programmable read-only locking mechanism called "static lock bytes". They are called static because their position in memory is fixed.

When data memory is larger than 16 blocks (64 bytes), also "dynamic lock bytes" are required. They are located starting at address 7Ah (4kbit version). Block lock granularity is 1 block per bit for the first 16 blocks, 2 blocks per bit for the remaining blocks.

Lock bits are OTP, i.e. setting bits to 1b is an irreversible operation. Bits at 0b can be set to 1b through a WRITE operation, the result being a bit-wise OR with the current value.

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Lock bits apply only to RF interface, as SPI / I<sup>2</sup>C interface has unlimited access to user data area.

- Lock 0 byte locks 8 blocks starting from address 00h where lock bit 0 locks block on address 00h
- Lock 1 byte locks 8 blocks starting from address 08h where lock bit 0 locks block on address 08h
- Lock 2 byte locks 16 blocks starting from address 10h where lock bit 0 locks block on address 10h and 11h
- Lock 3 byte locks 16 blocks starting from address 20h where lock bit 0 locks block on address 20h and 21h
- Lock 4 byte locks 16 blocks starting from address 30h where lock bit 0 locks block on address 30h and 31h
- Lock 5 byte locks 16 blocks starting from address 40h where lock bit 0 locks block on address 40h and 41h
- Lock 6 byte locks 16 blocks starting from address 50h where lock bit 0 locks block on address 50h and 51h
- Lock 7 byte locks 16 blocks starting from address 60h where lock bit 0 locks block on address 60h and 61h
- Lock 8 byte locks 16 blocks starting from address 70h where lock bit 0 locks block on address 70h and 71h

Figure 32: Example of Lock Bits

Lock 0 byte					Lock 1 byte										
b7	b6	b5	b4	b3	b2	b1	b0	b7	b6	b5	b4	b3	b2	b1	b0
	locks block					locks block									
07h	06h	05h	04h	03h	02h	01h	00h	0Fh	0Eh	0Dh	0Ch	0Bh	0Ah	09h	08h

### **Capability Container**

Block 03h in AS3956 EEPROM contains the Capability Container (CC), pre-programmed during IC production according to NFC Forum Type 2 Tag specifications [T2T]. CC bits are OTP, i.e. setting bits to 1b is an irreversible operation. Bits at 0b can be set to 1b through a WRITE operation, the result being a bit-wise OR with the current value.

Figure 33 and Figure 34 show the Capability Container content at delivery.

Figure 33: CC Content at Delivery (4kbit EEPROM)

	Byte number in block						
Block address	0	1	2	3			
03h	E1h	10h	3Bh	00h			

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# **Configuration Bytes**

The Configuration bytes are used to define AS3956 operating options. AS3956 is delivered by **ams** with default settings.

### **Authentication Password**

The Authentication password block (bytes RFP0, RFP1, RFP2, and RFP3) contains the 32-bit password. This password is used for authentication over RF side. The NFC tag is set into AUTHENTICATED state when a write command is issued via the RF to write password address with the data that has same content as the data stored in Authentication password block. If the NFC tries to authenticate with a wrong password, AS3956 shall not respond and returns into SENSE / SLEEP state and the value of the AUTH CNT is decreased.

The password can be overwritten via RF only in AUTHENTICATED state and can always be set via SPI / I<sup>2</sup>C. Configuration register AUTH\_CFG defines access rights controlled by the password. The RF password can't be read via RF.

The authentication for read or write is required only to the memory portion defined by AUTH\_LIM. The chip is no longer in AUTHENTICATED state when the tag leaves SELECTED state.

An attempt to read the password block will return zeroes. The authentication does not override permissions set by the lock bits. Authentication also does not restrict access over SPI / I<sup>2</sup>C in any way.

Authentication can be configured using configuration bits in AUTH\_CFG and AUTH\_LIM bytes.

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### Configuration Byte CHIP\_KILL

Figure 34: Configuration Byte CHIP\_KILL

Conf. Bit	Name	Default	Function	Note
b7	chip_kill_2	0	1: Tunneling and Extended mode are disabled	
b6	chip_kill_1	0	1: RF communication part is disabled	
b5	rfu	0		
b4	rfu	0		
b3	rfu	0		
b2	rfu	0		
b1	rfu	0		
b0	rfu	0		

### Note(s):

1. This byte can always be accessed for read and write via the SPI /  $l^2C$  and can't be accessed for read and write from the RF side.

By setting CHIP\_KILL byte the RF communication part of the chip or Tunneling and Extended mode will be disabled permanently. At its initial state, the CHIP\_KILL byte is set to value 00h. The value of this byte can be changed via SPI / I<sup>2</sup>C. If bit b6 is set to value 1, the RF part of the chip shall be disabled and AS3956 will not respond to any command received from a NFC device. By setting bit b7 to 1, Tunneling and Extended mode will be disabled.

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### Configuration Byte AUTH\_CNT

Figure 35: **Configuration Byte AUTH\_CNT** 

Conf. Bit	Name	Default	Function	Note
b7	rfu	0		
b6	auth_cnt2<2>	1		
b5	auth_cnt2<1>	1	Authentication counter 2	
b4	auth_cnt2<0>	1		
b3	rfu	0		
b2	auth_cnt1<2>	1		
b1	auth_cnt1<1>	1	Authentication counter 1	
b0	auth_cnt1<0>	1		

#### Note(s):

1. This byte can always be accessed for read and write via the SPI /  $I^2C$  and can't be accessed for read and write from the RF side.

This byte indicates the number of allowed unsuccessful authentication attempts over RF available before disabling the chip. The byte consists of two separate counters where the second counter is a copy of the first counter.

These counters are updated at each failed authentication. At each successful authentication, counters are reset to 7 and, at each unsuccessful authentication attempt, counters are decreased by one. If the value of the counters reaches 0, the chip will be permanently locked and cannot be authenticated any longer over the RF field. The chip will also be locked in case the two counter values don't match. The lock can always be cleared via SPI / I<sup>2</sup>C interface.

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#### Configuration Byte AUTH\_LIM

Figure 36: Configuration Byte AUTH\_LIM

Conf. Bit	Name	Default	Function	Note
b7	auth_lim<7>	1		
b6	auth_lim<6>	1		
b5	auth_lim<5>	1		
b4	auth_lim<4>	1	AUTH_LIM defines the block address above	
b3	auth_lim<3>	1	which password verification is required.	
b2	auth_lim<2>	1		
b1	auth_lim<1>	1		
b0	auth_lim<0>	1		

#### Note(s):

AUTH\_LIM defines the block address above which password verification is required. Valid address range for the AUTH\_LIM byte is from 00h to FFh. If AUTH\_LIM is set to a block address higher than the last block of the EEPROM address space, the password protection is effectively disabled. Addresses above the limit are protected for read / write depending on <code>auth\_r</code> and <code>auth\_w</code> values. If no bits are set, password protection is disabled.

If the NFC device tries to access protected blocks without authenticating first, then:

- If only protected blocks are accessed, AS3956 will not respond
- If protected and unprotected blocks are accessed<sup>1</sup>, AS3956 will return actual stored values only for the unprotected portion, and zeroes for the protected portion.

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<sup>1.</sup> This byte can always be accessed for read and write via SPI / I<sup>2</sup>C and can be accessed for read and write from the RF side if chip is in AUTHENTICATED state and configuration bit *auth\_set* is 1.

<sup>1.</sup> This can occur, for instance, with a READ command crossing the border between protected and unprotected memory.



### Configuration Byte AUTH\_CFG

Figure 37: **Configuration Byte AUTH\_CFG** 

Conf. Bit	Name	Default	Function	Note
b7	rfu	0		
b6	rfu	0		
b5	rfu	0		
b4	rfu	0		
b3	rfu	0		
b2	rfu	0		
b1	auth_w<1>	0	Authentication is required for writing	
b0	auth_r<0>	0	Authentication is required for reading	

#### Note(s):

1. This byte can always be accessed for read and write via SPI /  $I^2C$  and can be accessed for read and write from the RF side if chip is in AUTHENTICATED state and configuration bit *auth\_set* is 1.

> Bits *auth\_w* and *auth\_r* define for which operations the authentication is needed. If a lock bit is set for a certain block, then write cannot be performed even if IC is in AUTHENTICATED state. This means that lock bits overrule authentication.

**Configuration Byte SENSR1** 

Figure 38: **Configuration Byte SENSR1** 

Conf. Bit	Name	Default	Function	Note
b7	sens_res<15>	0		
b6	sens_res<14>	0		
b5	sens_res<13>	0		
b4	sens_res<12>	0	SENS DES response bute 2 an SENS DEC	
b3	sens_res<11>	0	SENS_RES response byte 2 on SENS_REQ	
b2	sens_res<10>	0		
b1	sens_res<9>	0		
b0	sens_res<8>	0		

## Note(s):

1. This byte can always be accessed for read and write via SPI /  $I^2C$  and can be accessed for read and write from the RF side if  $rfcfg\_en$ is set to 1.

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## **Configuration Byte SENSR2**

Figure 39: **Configuration Byte SENSR2** 

Conf. Bit	Name	Default	Function	Note
b7	sens_res<7>	0		
b6	sens_res<6>	1	SENS_RES response byte 1 on SENS_REQ	
b5	sens_res<5>	0		
b4	sens_res<4>	0		
b3	sens_res<3>	0		
b2	sens_res<2>	1		
b1	sens_res<1>	0		
b0	sens_res<0>	0		

#### Note(s):

1. This byte can always be accessed for read and write via SPI / I<sup>2</sup>C and can be accessed for read and write from the RF side if rfcfg\_en is set to 1.

# **Configuration Byte SELR**

Figure 40: **Configuration Byte SELR** 

Conf. Bit	Name	Default	Function	Note
b7	sel_res<7>	0		
b6	sel_res<6>	0		
b5	sel_res<5>	0		
b4	sel_res<4>	0	SEL_RES response on Cascade Level 1/2	
b3	sel_res<3>	0		
b2	sel_res<2>	0		This bit is not used, as cascade bit 3 in SEL_RES CL1 is fixed to 1, and to 0 in SEL_RES CL2
b1	sel_res<1>	0		
b0	sel_res<0>	0		

### Note(s):

1. This byte can always be accessed for read and write via SPI / I<sup>2</sup>C and can be accessed for read and write from the RF side if rfcfg\_en is set to 1.

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## Configuration Byte IC\_CFG0

Figure 41: Configuration Byte IC\_CFG0

Conf. Bit	Name	Default	Function	Note
b7	sInt_mod	0	1: Enable silent mode	
b6	sInt_vl<2>	0		
b5	sInt_vl<1>	0	Silent mode voltage level (see Silent Mode)	
b4	sInt_vI<0>	0		
b3	arbit_mod	0		
b2	i2c_addr3<2>	0		
b1	i2c_addr2<1>	0	I <sup>2</sup> C slave address	
b0	i2c_addr1<0>	0		

#### Note(s):

Bit sInt\_mod enables Silent mode. In this mode, the supply pin VP\_IO is being observed. If voltage is below the level defined in sInt\_vI<2:0>, then Silent mode is activated. This means that RF part of the IC is turned off and stops being responsive to incoming RF commands.

Voltage threshold settings on VP\_IO are shown in Figure 42.

Figure 42: Silent Mode Threshold Voltage Levels

sInt_vl<2:0>	Typ. Voltage Threshold [V]
000b	1.42
001b	1.62
010b	1.82
011b	2.23
100b	2.53
101b	2.74
110b	3.04
111b	3.65

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<sup>1.</sup> This byte can always be accessed for read and write via SPI / I<sup>2</sup>C and can be accessed for read and write from the RF side if rfcfg\_en is set to 1. Bit arbit\_mod can be modified after initialization over SPI / I<sup>2</sup>C.



The voltage level of the supply on VP\_IO is measured when tag enters RF field. The selected voltage level threshold can be properly measured only if the RF field is strong enough to provide sufficient supply voltage level. When small antennas are used, it is advisable to set lower threshold.

The  $i2c_addr$  bits represent lower three bits of the  $I^2C$  address. The upper four bits of the  $I^2C$  address that represent a group shall be set to 1010b.

Configuration Byte IC\_CFG1

Figure 43: Configuration Byte IC\_CFG1

Conf. Bit	Name	Default	Function	Note
b7	en_rx_crc	0	1: CRC stored in the buffer in the tunneling mode	
b6	vreg<4>	0		
b5	vreg<3>	0		
b4	vreg<2>	0	Voltage level for voltage regulator VP_REG (see Figure 16)	
b3	vreg<1>	0		
b2	vreg<0>	0		
b1	rreg<1>	0	Output resistance value for voltage regulator VP_REG	
b0	rreg<0>	0	(see Figure 15)	

## Note(s):

If bit *en\_rx\_crc* is set to 1 then the CRC shall be part of the message in the buffer. This implies that maximum message effective length is reduced to 30 bytes. CRC check is performed regardless of the value of the *en\_rx\_crc* bit.

Configuration Byte IC\_CFG2

Figure 44: Configuration Byte IC\_CFG2

Conf. Bit	Name	Default	Function	Note
b7	rfcfg_en	1	1: Enables personalization / configuration over RF	
b6	tun_mod	0	1: Enables Tunneling Mode	
b5	ext_mod	0	1: Enables Extended Mode	

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<sup>1.</sup> This byte can always be accessed for read and write via SPI / I<sup>2</sup>C and can be accessed for read and write from the RF side if rfcfg\_en is set to 1.



Conf. Bit	Name	Default	Function		Note
b4	nak_on_crc_parity	0	1: Defines error hand	lling and response	
b3	auth_set	0	1: Configuration of the authentication settings is enabled from RF side		
b2	selr_b6_inv	0	1: Inverts bit 6 in SEL_RES response on Cascade Level 2		
b1	powm<1>	0	00: Power Mode 0	10: NA 11: Power Mode 3-	
b0	powm<0>	0	- Default Power Mode 01: NA	External Supply Used to Power EEPROM and Logic	

#### Note(s):

1. This byte can always be accessed for read and write via SPI / I<sup>2</sup>C and can be accessed for read and write from the RF side if rfcfg\_en is set to 1. Bits  $tun\_mod$  and  $ext\_mod$  represents a default value stored in a volatile memory which can be modified after initialization over SPI / I<sup>2</sup>C.

> Bit rfcfg\_en enables the personalization process during production at customer facilities. When this bit is set to 0, the modification of the last two blocks is not possible anymore over the RF field.

> If auth\_set is set then changing of authenticated setting (authentication limits, read/write permission) is enabled over the RF after successful authentication. Password can always be changed via the RF side if tag is in authenticated state regardless of the value of read/write bits.

> Bit nak\_on\_crc\_parity configures error handling mechanism as described in Error Handling.

> Bit selr\_b6\_inv configures SEL\_RES response on Cascade Level 2. If selr b6 invis set to 1, bit b6 in SEL RES response on Cascade Level 2 will be inverted, otherwise it will be set as configured in SELR byte.

> Bits powm<1:0> are setting power modes as defined in Power Management.

Configuration Bytes MIRQ\_0 and MIRQ\_1

These two bytes define the default value of the volatile memory for Mask Interrupt Register 0 and Mask Interrupt Register 1 registers. The default value for both bytes is 00h. These bytes can always be accessed for read and write via the SPI / I<sup>2</sup>C and can be accessed for read and write from the RF side if rfcfg\_en is set to 1.

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### 32 Byte Buffer

The AS3956 has an internal 32-byte buffer used to:

- Temporarily hold the values of the UID, SENSR1, SENSR2, SELR which are copied from EEPROM and are used during anti-collision
- · Store data received via RF
- For data exchange between an NFC device and an MCU connected to the AS3956

The buffer has a position pointer which is set automatically after each successful write, read or clear operation and points to the last byte of the data available for read/transmit.

### **AS3956 Communication Modes**

AS3956 supports three different modes. The basic communication mode is a standalone mode where AS3956 can behave as a standalone NFC tag without MCU intervention. The other two modes (Tunneling and Extended mode) represent modification of the communication in SELECTED state. The anti-collision process is the same for all three modes.

It is possible to change the mode of operation at any time. In case Tunneling and Extended mode are both enabled, Tunneling mode has priority over Extended mode.

### Standalone NFC Type 2 Tag Mode

If neither of the two modes are enabled (Tunneling and Extended mode) in IC Configuration Register 2, the tag is in standalone mode. In this mode, all RF incoming commands address the internal EEPROM. In this mode, it is always possible to connect the MCU since all other functionalities of AS3956 are not limited by the communication modes. The main purpose of this mode is to use the AS3956 as a standalone chip or a chip in combination with MCU where the MCU is used for managing AS3956 configuration and memory content.

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### **Tunneling Mode**

Tunneling mode enables transparent data transfer between NFC device and MCU. In this mode, the internal EEPROM cannot be accessed via RF and any type of data received will be forwarded to MCU when the tag is in SELECTED state. An error during the reception will trigger a corresponding interrupt. In this mode the MCU shall take care for the correct response. For this purpose, the MCU may issue an ACK or a different type NAK response using implemented commands.

By enabling this mode, the MCU can emulate NFC type 2 tags, NFC type 4 tags, ISO14443A Level 3 cards, ISO14443A Level 4 cards, and also implement higher level protocols such as [PHDC].

Tunneling mode can be configured by setting Configuration Byte IC\_CFG2 in EEPROM or the corresponding register (IC Configuration Register 2).

This mode also allows access to the internal EEPROM via the SPI / I<sup>2</sup>C during RF communication.

The basic assumption of Tunneling mode is that MCU is responsible for generating the response and that AS3956 takes care of the response synchronization over RF. For this reason, AS3956 has a possibility to transmit ACK and NACK by issuing a direct command (see section Direct Commands). The MCU can also transmit data by writing the data into the buffer and issuing a Transmit command. The implementation of Tunneling mode also requires the handling of the SLP\_REQ command since all the received data in SELECTED state are stored in the buffer and will not be processed by AS3956. This also implies that MCU has to take care of correct transition of the tag into SLEEP or SENSE state by using one of the three available commands Go To Sleep, Go To Sense and Go To Sense / Sleep.

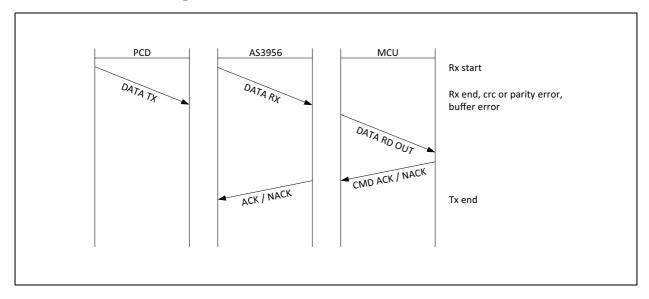
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### **Data Transaction in Tunneling Mode**

Figure 45 shows an example of how communication in Tunneling mode should be implemented.

Figure 45: Read First, then Acknowledge



ACK and NACK responses can be replaced by data, in case of an incoming READ command.

Relevant Registers, Interrupts and Commands

## Registers:

• Buffer Status Register 1 and Buffer Status Register 2 (data length and error type)

### Interrupts:

- Rx start (I\_rxs bit in Interrupt Register 1)
- Rx end, Tx end (resp. I\_rxe and I\_txe bits in Interrupt Register 0)
- CRC, parity and framing interrupt (resp. I\_crc\_err, I\_par\_err and I\_frm\_err bits in Interrupt Register 1)
- Buffer error (*I\_bf\_err* in Interrupt Register 1)
- SPI / I<sup>2</sup>C buffer access error (I\_acc\_err in Interrupt Register 1)

#### **Commands:**

- Transmit ACK
- Transmit NACK 0-5
- Transmit Buffer
- Go To Sense
- Go To Sleep
- Go To Sense / Sleep

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#### **Extended Mode**

Extended mode enables communication between the NFC device and MCU by employing standard NFC Tag 2 Type READ and WRITE commands for data transfer RF to MCU and Buffer Load, Buffer Read, Clear Buffer and Transmit Buffer commands for data transfer MCU to NFC device. The purpose of this communication mode is to provide a simple data transfer mechanism between a NFC device and a MCU while guaranteeing correct timing and synchronization. This is achieved by implementing a robust handshake mechanism.

This mode uses a part of the memory address space that is out of range of the internal physical memory. The communication between a NFC device and a MCU can be performed by using WRITE/READ commands on address FCh – FFh. Block addresses FCh to FFh, each block having 4 bytes, are mapped to the first 16 bytes of the internal Buffer. Writing to these addresses will write to the Buffer and reading will read from Buffer. Data with CRC or any other error will not be placed in the Buffer. Each successful write operation on any of these blocks, AS3956 will automatically reply with ACK. Maximum packet size for data from NFC device to MCU is 16 bytes and for data from MCU to NFC device is 12 bytes, as the last 4 bytes of the Read response, which is 16 bytes, are reserved for flags.

Error handling in Extended mode is defined in Error Handling. Data received from RF side are kept available until the MCU reads the data. The implemented asynchronous transmission protocol arbitrates on overlapping memory accesses (producer-consumer principle) and complies with timing constraints of both RF and SPI / I<sup>2</sup>C protocols regardless of the MCU performance.

Extended mode can be configured by setting Configuration Byte IC\_CFG2 in EEPROM or the corresponding register (IC Configuration Register 2).

Extended mode uses an address space above the address space of the internal EEPROM. It is then possible for a NFC device to perform accesses to AS3956 internal memory and data transfer to/from the MCU, without switching modes. This feature allows the NFC device e.g. to request to the MCU a switch to Tunneling mode with a simple WRITE command. The extended mode communication employs a built-in buffer for communication. Access to buffer from RF and SPI / I<sup>2</sup>C is mutually exclusive. AS3956 ensures that buffer content shall be kept as long as the AS3956 is powered (even in case RF field is not present) and as long the tag is in SELECTED state. In case the RF field is switched off and then on again, the buffer content will be reset.

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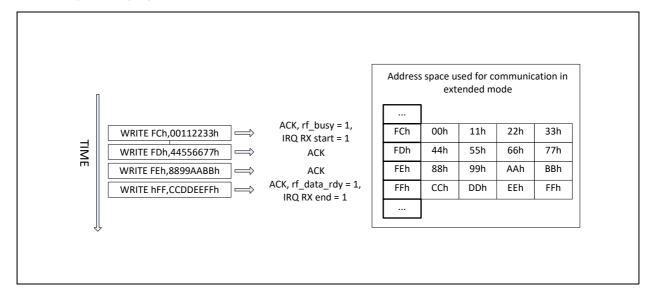


#### NFC Device to MCU Data Flow Protocol

For the data transmission from NFC device to the MCU employing the Extended mode, a NFC WRITE shall be used. Each data transfer from NFC device is comprised of four WRITE commands starting from address FCh and ending at address FFh. The protocol implemented on a NFC device is expected to always start the data transmission at address FCh, which signals the beginning of the communication, and end at address FFh.

Figure 46 depicts regular implementation of the Extended mode using the WRITE commands.

Figure 46:
Address Space Employed for Communication



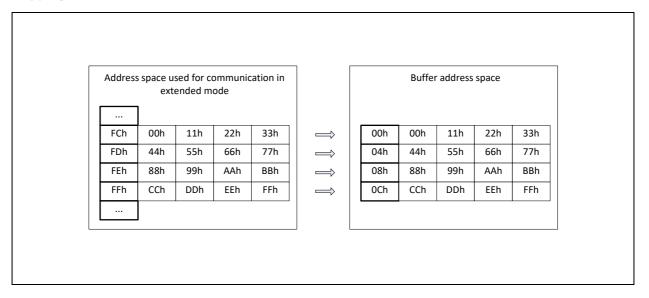
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Assuming that the internal buffer is empty, the NFC device may start with data transmission by sending a WRITE command on address FCh. When the first block is written, the rf\_busy flag is set and Rx start interrupt is triggered. At this point, the buffer cannot be accessed over SPI / I<sup>2</sup>C until the entire write message is received which is assumed to be complete when NFC device sends a write command to block FFh. At this point, an Rx end interrupt is triggered. This implies that a minimum two messages must be received from a NFC device in order to successfully complete a message. If a WRITE command is received on address FFh before a WRITE command to address FCh, AS3956 will assume that an error has occurred and will respond as described in Error Handling in Extended Mode.

When the reader writes into the last block FFh, rf\_data\_rdy flag is set and the reader cannot change the buffer content until the MCU reads the content of the block and clears the rf\_data\_rdy flag. Any additional reception of WRITE commands from NFC device, prior to MCU reading out the buffer content, shall result in a response as defined in Error Handling. The blocks from internal memory address space are directly mapped into buffer space as shown on Figure 47.

Figure 47:
Mapping of Data Received into Buffer

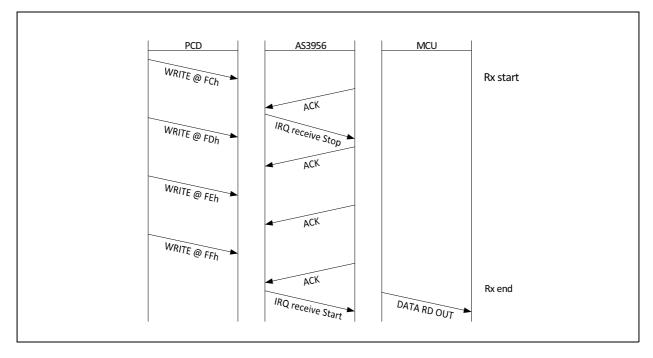


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When MCU reads out the data from the buffer, data will be sent to MCU in the same order as they were stored in the buffer starting from address 00h. When MCU has read all buffer content, it shall issue a Clear Buffer command to clear the flag rf\_data\_rdy. At this point, a new data message can be received.

Figure 48: Data Reception in Extended Mode



#### MCU to NFC Device Data Flow Protocol

NFC devices can receive data from a MCU through AS3956 by using standard READ commands.

Prior to writing data into the buffer, the MCU shall issue a Clear Buffer command to AS3956 to ensure data are correctly mapped into the buffer. To start data transmission, the MCU shall issue then a Transmit Buffer command. In this way, the flag io\_data\_rdy is set and data can be transmitted to the reader. The transmission of the data from the tag to the NFC device is done by issuing a READ command on block FCh. The fourth block being read during the read command contains the status flags of the ongoing communication.

NFC devices can receive data from a MCU through AS3956 by using standard READ commands.

Prior to writing data into the buffer, it is advisable that to issue a Clear Buffer command to AS3956 to ensure data are correctly mapped into the buffer. MCU can trigger data transmission by writing three words of data into the buffer at addresses FCh-FEh, and issuing a Transmit Buffer command. This will also set *io\_data\_rdy* flag. The transmission of the data from the tag to the read is done by issuing a read command on word 0xFC.

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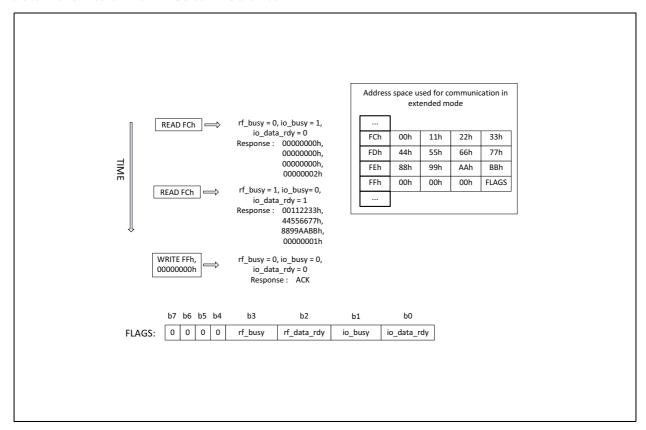
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The NFC device can then retrieve the data from the buffer by sending a READ command to address FCh. The fourth word contains the status flags as shown in Figure 49.

Figure 49: **Data Transmission from MCU to NFC Device** 



When the NFC device has successfully read all data from the buffer, it shall clear the buffer and prepare for further data transfer by issuing a WRITE command to address FFh. This will trigger a Tx end interrupt.

If a READ command is received on address FCh prior to the Transmit Buffer command, AS3956 will return zero data, io\_busy set to 1 and io\_data\_rdy set to 0. A NFC device can then poll AS3956 by continuously sending READ commands at address FCh and waiting until the last word equals 01h.

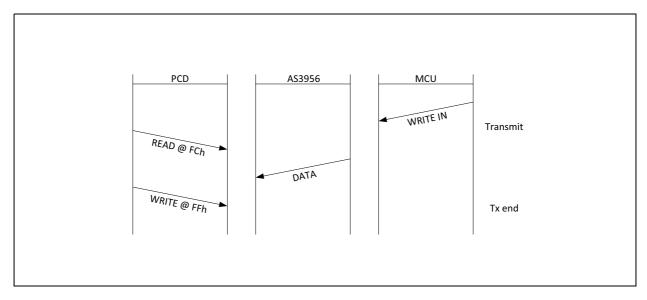
A READ command can be issued only to address FCh. Issuing a READ command to any other address than FCh while in Extended mode shall be treated as an error.

In Extended mode, it is assumed that AS3956 will always receive 16 bytes and transmit 12 bytes of data, 3 empty bytes and 1 byte for FLAGS. If the message size differs in any direction, then the MCU or NFC device are responsible for proper error management.

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Figure 50:
Data Transmission in Extended Mode



If MCU decides to update the buffer before the NFC device issues a WRITE command to address FFh, a *l\_acc\_err* interrupt will be triggered, signaling that buffer cannot be accessed (see Interrupt Register 1).

Relevant Registers, Interrupts and Commands

## **Relevant Registers:**

• Buffer Status Register 1 (status flags: rf\_busy, rf\_data\_rdy, io\_data\_rdy)

## **Relevant Interrupts:**

- Rx start (I\_rxs bit in Interrupt Register 1)
- Rx end, Tx end (resp. I\_rxe and I\_txe bits in Interrupt Register 0)

### **Commands:**

- Transmit Buffer
- Clear Buffer

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## **Extended Mode Timing Diagram**

Figure 51:
RF to MCU Data Transfer in Extended Mode

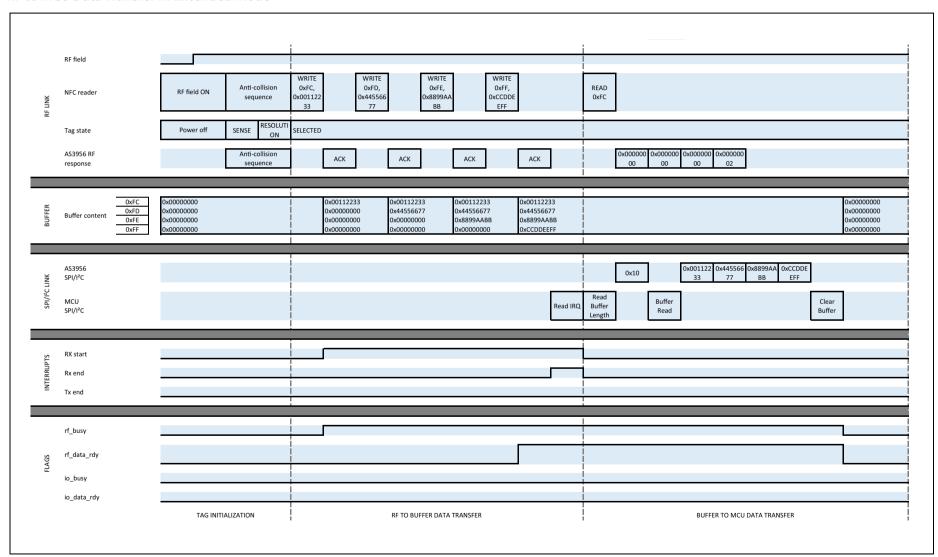
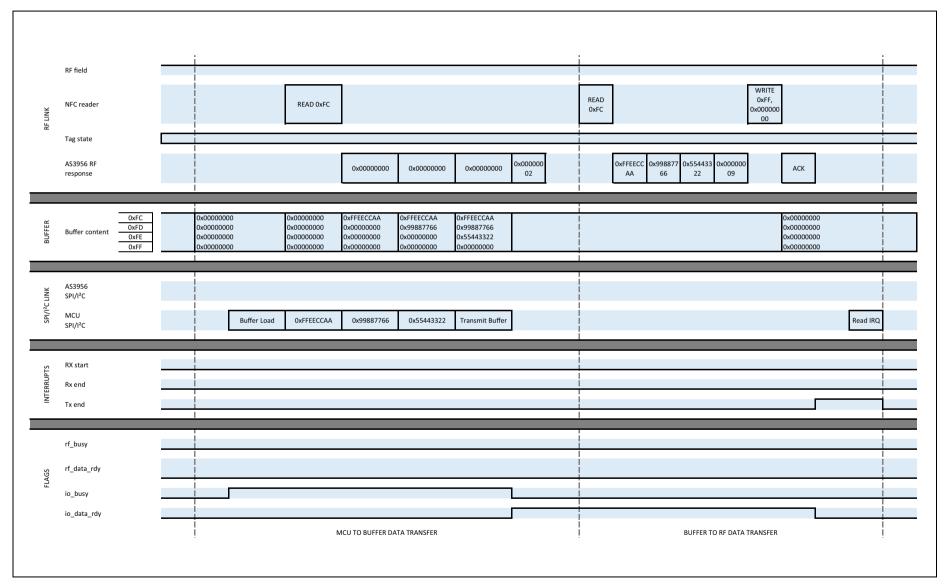




Figure 52: MCU to RF Data Transfer in Extended Mode



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## **Implementation Recommendations**

While in Extended mode, the NFC device shall not issue a WRITE command to the address space of the internal EEPROM until the buffer is empty. The NFC device can issue a READ command to check internal status flag (io\_busy = 0), before writing to EEPROM.

It is also not allowed to interleave data communication in Extended mode (e.g. writing to addresses FCh-FFh) and issue a WRITE command to internal EEPROM. If case this happens, writing to internal EEPROM would be successful, but the buffer content would be lost.

Reading status flags is always allowed.

## **Error Handling**

Figure 53 shows how different type of errors in Standalone and Extended communication modes are handled and what is the resulting state of the tag.

Figure 53: Error Handling

Command	Condition	AS3956 nak_on_crc_parity=0	AS3956 nak_on_crc_parity=1 (empty fields have same reply as nak_on_crc_parity=0)
Any	Bit Coding Error	No Response, SLEEP	
Any	Incomplete Frame	No Response, SLEEP	
T2T Read	Parity Error	No Response, SLEEP	NAK_1, SLEEP
T2T Read	CRC Error	No Response, SLEEP	NAK_1, SLEEP
T2T Read	1 Byte Frame (no CRC)	No Response, SLEEP	
T2T Read	Empty frame (only CRC bytes)	No Response, SLEEP	
T2T Read	Missing address	No Response, SLEEP	
T2T Read	Too long frame	No Response, SLEEP	
T2T Read	Memory fully locked	Send Block Content	
T2T Read	Memory partially locked	Send Block Content	
T2T Read	Memory fully protected	NAK_4, SLEEP	
T2T Read	Memory partially protected	Send unprotected memory a with zero bytes	is is, replace protected memory
T2T Read	Memory address range fully not existent	NAK_0, SLEEP	

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Command	Condition	AS3956 nak_on_crc_parity=0	AS3956 nak_on_crc_parity=1 (empty fields have same reply as nak_on_crc_parity=0)
T2T Read	Memory address range partially not existent	Send existing memory appended with zero bytes	
T2T Read	EEPROM access collision	NAK_5, SLEEP	
T2T Read	No Error	Send Block Content	
T2T Write	Parity Error	No Response, SLEEP	NAK_1, SLEEP
T2T Write	CRC Error	No Response, SLEEP	NAK_1, SLEEP
T2T Write	1 Byte Frame (no CRC)	No Response, SLEEP	
T2T Write	2 Byte Frame with correct CRC	No Response, SLEEP	
T2T Write	Missing address and data	No Response, SLEEP	
T2T Write	Missing data	No Response, SLEEP	
T2T Write	Incomplete data	No Response, SLEEP	
T2T Write	Too long frame	No Response, SLEEP	
T2T Write	Memory fully locked	NAK_0, SLEEP	
T2T Write	Memory partially locked	Cannot occur	
T2T Write	Memory fully protected	NAK_4, SLEEP	
T2T Write	Memory partially protected	Cannot occur	
T2T Write	Memory address range fully not existent	NAK_0, SLEEP	
T2T Write	Memory address range partially not existent	Cannot occur	
T2T Write	EEPROM access collision	NAK_5, SLEEP	
T2T Write	No Error	ACK, SELECTED	
T2T Sector Select 1	Parity Error	No Response, SLEEP	NAK_1, SLEEP
T2T Sector Select 1	CRC Error	No Response, SLEEP	NAK_1, SLEEP
T2T Sector Select 1	1 Byte Frame (no CRC)	No Response, SLEEP	
T2T Sector Select 1	Empty frame (only CRC bytes)	No Response, SLEEP	

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Command	Condition	AS3956 nak_on_crc_parity=0	AS3956 nak_on_crc_parity=1 (empty fields have same reply as nak_on_crc_parity=0)
T2T Sector Select 1	Missing second byte	No Response, SLEEP	
T2T Sector Select 1	Incorrect second byte (not FFh)	No Response, SLEEP	
T2T Sector Select 1	Too long frame	No Response, SLEEP	
T2T Sector Select 1	Only 1 sector available	NAK_0, SLEEP	
T2T Sector Select 2	Parity Error	No Response, SLEEP	NAK_1, SLEEP
T2T Sector Select 2	CRC Error	No Response, SLEEP	NAK_1, SLEEP
T2T Sector Select 2	1 Byte Frame	No Response, SLEEP	
T2T Sector Select 2	Empty frame (only CRC bytes)	No Response, SLEEP	
T2T Sector Select 2	Missing sector number	No Response, SLEEP	
T2T Sector Select 2	Missing RFU bytes	No Response, SLEEP	
T2T Sector Select 2	Too few RFU bytes	No Response, SLEEP	
T2T Sector Select 2	Too long frame	No Response, SLEEP	
T2T Sector Select 2	Selected sector not existent (cannot happen for AS3956)	No Response, SLEEP	
T2T Sector Select 2	No Error (cannot occur for AS3956)	No Response, SLEEP	
Unknown Command Code	Parity Error	No Response, SLEEP	NAK_1, SLEEP
Unknown Command Code	CRC Error	No Response, SLEEP	NAK_1, SLEEP
Unknown Command Code	No Error	No Response, SLEEP	



Figure 54: Error Handling in Extended Mode

Command	Condition	Error Type
Write buffer (T2T Write)	Start with FD, FE or FF	NAKO, SLEEP
Write buffer (T2T Write)	Write when io_data_rdy=1 or rf_data_rdy=1	NAKO, SLEEP
Clear buffer (T2T Write on block FFh)	Write none zero data	NAKO, SLEEP
Read buffer (T2T read on block FCh)	Read on FD, FE, FF	NAKO, SLEEP
Read buffer (T2T read on block FCh)	Buffer access collision	NAK5, SLEEP
Write buffer (T2T Write)	Buffer access collision	NAK5, SLEEP
Clear buffer (T2T Write on block FFh)	Buffer access collision	NAK5, SLEEP

## **Wired Interfaces**

AS3956 host interface can be configured to be either SPI or I<sup>2</sup>C at production (Fabrication Data FAB\_CFG0). In both cases, the /SS signal is also used to control the IC power state. By pulling the /SS low, the chip interface or the chip itself is enabled / powered (see Power Management). Note that interrupting SPI / I<sup>2</sup>C operations or issuing incomplete command sequence from the MCU may result in corrupted data content. For more information on EEPROM and buffer data reading and writing see EEPROM Read and Write and Data Buffer sections.

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# SPI / I<sup>2</sup>C Access Modes

Figure 55: Access Modes

	MODE Byte (com. bits)											
Mode	MODE			Trailer				MODE Related Data				
	M2	M1	МО	C4	С3	C2	C1	C0				
Register Write	0	0	0	A4	А3	A2	A1	A0	Data	byte(s)		
Register Read	0	0	1	A4	А3	A2	A1	A0	Data byte(s)			
EEPROM Write	0	1	0	0	0	0	0	0	Block address 4 bytes of blo			
EEPROM Read	0	1	1	1	1	1	1	1	Block address byte N*4 bytes			
Buffer Load	1	0	0	х	х	х	х	х	Data byte(s)			
Buffer Read	1	0	1	х	х	х	х	х	Data byte(s)			
COMMAND Mode	1	1	C5	C4	C3	C2	C1	C0				



#### **SPI Interface**

Communication between AS3956 and microcontroller can be done via a four-wire Serial Peripheral Interface (SPI) and an additional interrupt signal. AS3956 acts an SPI slave device, and it can request MCU attention by sending an interrupt (pin IRQ). Please note a 100k ohm pull down resistor is recommended to be connected to the IRQ pin to prevent IRQ from floating when /SS is high.The SCLK frequency can be between 100 kHz and 5 MHz.

In addition to Schmitt triggers on all digital input lines a glitch suppression filter is implemented on the SCLK input and suppresses glitches of length  $T_{\rm qs}$ .

Figure 56: SPI and Interrupt Signals

Name	Signal	Signal Level	Description
/SS	Digital Input with pull-up	CMOS	SPI enable (active low)
MOSI	Digital Input	CMOS	Serial data input
MISO	Digital Output with tristate	CMOS	Serial data output
SCLK	Digital Input	CMOS	Clock for serial communication
IRQ	Digital Output	CMOS	Interrupt output pin (active high)

SPI interface is in reset mode when signal /SS is high, and it is enabled when /SS is low. It is recommended to keep signal /SS high whenever the SPI interface is not used. MOSI is sampled at the falling edge of SCLK. All communication is done in 8-bit blocks (bytes). First three bits of first byte transmitted after /SS high to low transition define SPI operation mode. MSB bit is always transmitted first (valid for address and data). Read and Write modes support address auto incrementing, which means that in case some additional data bytes may be sent (read), they are written to (read from) addresses incremented by 1 after the address and first data byte.

SPI interface supports the following modes:

- Internal registers read and write
- · EEPROM read and write
- Buffer read and write
- Direct commands

Note that in case when logic and EEPROM are supplied from the VP\_IO, the only SPI operations permitted are reading and writing of EEPROM and registers (see also Power Management).

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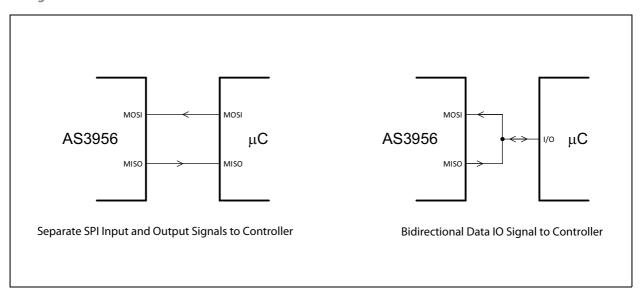
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MISO output is usually in tristate and it is only driven when output data is available. MOSI and MISO can then be externally shorted to create a bidirectional signal. When MISO output is in tristate, it is possible to switch on a pull down resistor RPD by activating option bit miso\_pd1 in IO Configuration Register.

Figure 57: **IO Signals to Controller** 



### Writing Data to Addressable Registers (Register Write Mode)

Following figures show waveforms of writing a single byte and writing multiple bytes with auto-incrementing address. After the SPI operation mode bits, the address of starting register to be written is provided. Then one or more data bytes are transferred from the SPI, always MSB first. The data byte is written in register on falling edge of its last clock. In case the communication is terminated by putting /SS high before a packet of 8 bits composing one byte is sent, writing of this register is not performed. In case the register on the defined address does not exist or it is a read-only register, no write is performed.

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Figure 58: SPI Communication: Writing a Single Register

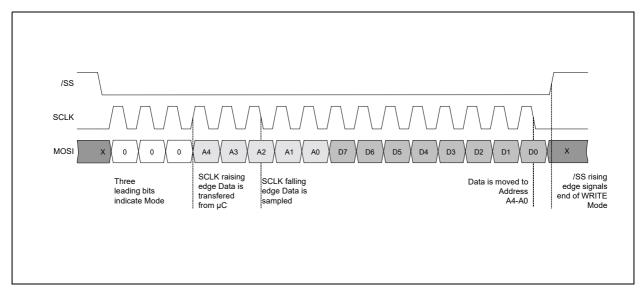
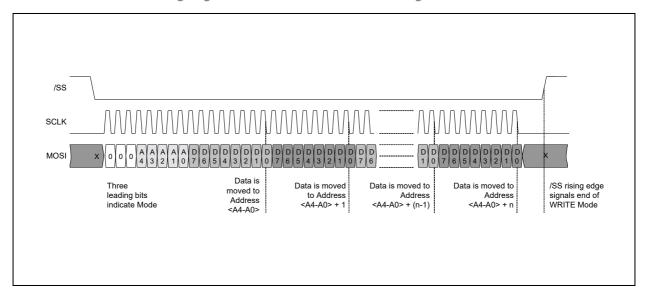


Figure 59: SPI Communication: Writing Register Data with Auto-Incrementing Address



Reading Data from Addressable Registers (Register Read Mode)

After the SPI operation mode bits, the register address to be read shall be provided, MSB first. Then one or more data bytes are transferred to MISO output, always MSB first. As in case of the write mode, also the read mode supports auto-incrementing addressing.

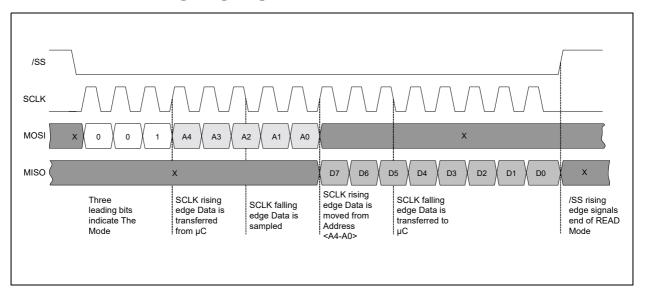
MOSI is sampled at the falling SCLK edge (as shown in the following diagrams); data to be read from AS3956 internal register is driven to MISO pin on rising edge of SCLK and is sampled by the master at the falling SCLK edge.

In case the register on defined address does not exist, all 0 data is sent to MISO. In the following figure an example of reading of a single byte is given.

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Figure 60: **SPI Communication: Reading a Single Register** 



## Writing and Reading of EEPROM Through SPI

EEPROM data can be read and written also through SPI interface. Arbitration between EEPROM access via the RF and SPI/I<sup>2</sup>C interface is performed on a first-come-first-serve basis as described in Interface Arbitration.

### **Word Address Byte**

Both EEPROM modes (Read and Write) use Word Address byte to define the address of the EEPROM word which is accessed. Seven MSB bits of the Address Byte are used to define the address; while the last bit is don't care (it is used to synchronize EEPROM access).

Figure 61: **EEPROM Block Address Byte** 

	В7	В6	В5	B4	В3	B2	B1	ВО
EEPROM Block Address	WA6	WA5	WA4	WA3	WA2	WA1	WA0	х

### **EEPROM Write**

In order to program an EEPROM block, six bytes shall be sent (mode byte, block address byte and 4 bytes of data, all of them MSB first). Actual EEPROM programming is started with rising /SS edge signal which terminates the EEPROM Write command.

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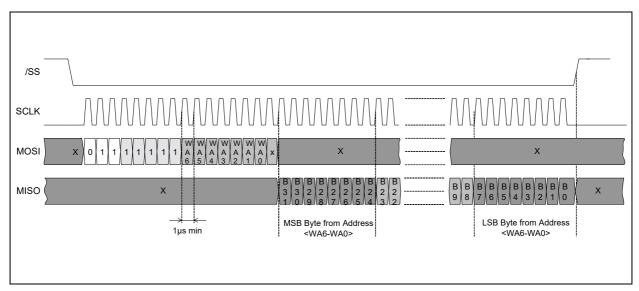


### **EEPROM Read**

In order to read data from EEPROM, first a mode byte is sent, followed by the block address byte (MSB first). Then one or more blocks of data with address auto-incrementing (packets of 4 bytes) are transferred to MISO output, also MSB first. MOSI is sampled at the SCLK falling edge; data to be read from AS3956 EEPROM is driven to MISO pin on SCLK rising edge and is sampled by the master at the SCLK falling edge. In case the block on the defined address does not exist, all 0 data is sent to MISO.

Please note that SCLK frequency should not exceed 1MHz during EEPROM Read (limited by EEPROM read access time).

Figure 62: Reading an EEPROM Block over SPI



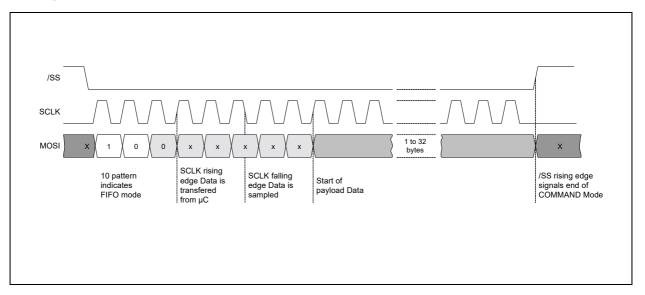
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### **Loading Transmission Data into Buffer**

Loading the transmitting data into the buffer is similar to writing data into an addressable registers. Difference is that in case of loading more bytes all bytes go to the buffer. The command mode code 100b indicates buffer write operation. A bit stream of 32 bytes of data can be transferred. The following figure shows how to load the transmission data into the buffer.

Figure 63: **Loading Data into Buffer over SPI** 



# Reading Received Data from Buffer

Reading received data from the buffer is similar to reading data from an addressable registers. Difference is that, in case of reading more bytes, they all come from the buffer. The command mode code 101b indicates buffer operations. In case the command is terminated by putting /SS high before a packet of 8 bits composing one byte is read that particular byte is considered read.

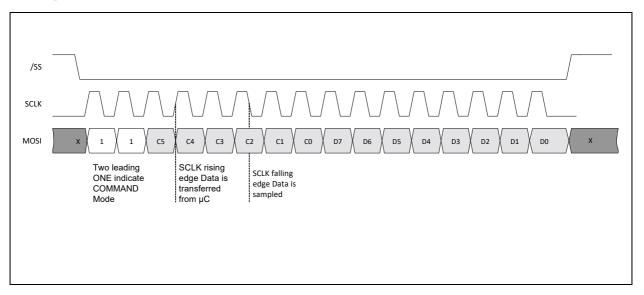
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### **Direct Command Mode**

Direct Command Mode is comprised of one command byte followed by argument byte. SPI operation mode bits 11b indicate Direct Command Mode. The following six bits define command code, sent MSB first. Last two bits in argument byte indicate success of the direct command. Value 01h of the argument byte indicates that command was accepted, while value 02h indicates rejected due to internal access priorities. The argument byte does not provide information on timing of the command execution.

Figure 64: Sending a Direct Command over SPI



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## **SPI Timing**

## Figure 65: **SPI Timing**

Symbol	Parameter	Min	Тур	Max	Unit	Note					
	General Timing (VP_IO= 3.3V, Temperature 25°C)										
T <sub>SCLK</sub>	SCLK period	200		10000	ns	See note (1)					
T <sub>SCLKL</sub>	SCLK low	80			ns						
T <sub>SCLKH</sub>	SCLK high	80			ns						
T <sub>gs</sub>	Glitch suppression on SCLK input	18		29	ns						
T <sub>SSH</sub>	SPI reset (/SS high)	50			ns						
T <sub>NCSL</sub>	/SS falling to SCLK rising	25 <sup>(2)</sup>			ns	First SCLK pulse					
T <sub>NCSH</sub>	SCLK falling to /SS rising	80			ns	Last SCLK pulse					
T <sub>DIS</sub>	Data in setup time	10			ns						
T <sub>DIH</sub>	Data in hold time	10			ns						
	Read Timing (VP_	IO= 3.3V, Te	mperature 2	5°C, Cload ≤	50pF)						
T <sub>DOD</sub>	Data out delay		20		ns						
T <sub>DOHZ</sub>	Data out to high impedance delay		20		ns						
	EEPROM Write	Timing (VP_	IO= 3.3V, Te	mperature 2	5°C)						
T <sub>EWS</sub>	EEPROM write time via SPI		8.3	9.5	ms	/SS rising edge to IRQ I_io_eewr					

### Note(s):

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 $<sup>1.\,</sup>T_{SCLK} = T_{SCLKL} + T_{SCLKH,} \,during \,\,EEPROM \,\,read \,\,the \,\,SCLK \,\,period \,\,has \,\,to \,\,be \,\,increased \,\,to \,\,1\mu s \,\,(this \,\,limitation \,\,is \,\,imposed \,\,by \,\,EEPROM \,\,read \,\,the \,\,SCLK \,\,period \,\,has \,\,to \,\,be \,\,increased \,\,to \,\,1\mu s \,\,(this \,\,limitation \,\,is \,\,imposed \,\,by \,\,EEPROM \,\,read \,\,the \,\,SCLK \,\,period \,\,has \,\,to \,\,be \,\,increased \,\,to \,\,1\mu s \,\,(this \,\,limitation \,\,is \,\,imposed \,\,by \,\,EEPROM \,\,read \,\,the \,\,SCLK \,\,period \,\,has \,\,to \,\,be \,\,increased \,\,to \,\,1\mu s \,\,(this \,\,limitation \,\,is \,\,imposed \,\,by \,\,EEPROM \,\,read \,\,the \,\,SCLK \,\,period \,\,has \,\,to \,\,be \,\,increased \,\,to \,\,1\mu s \,\,(this \,\,limitation \,\,is \,\,imposed \,\,by \,\,EEPROM \,\,read \,\,the \,\,SCLK \,\,period \,\,has \,\,to \,\,be \,\,increased \,\,to \,\,1\mu s \,\,(this \,\,limitation \,\,is \,\,imposed \,\,by \,\,EEPROM \,\,read \,\,the \,\,SCLK \,\,period \,\,has \,\,to \,\,be \,\,increased \,\,to \,\,1\mu s \,\,(this \,\,limitation \,\,is \,\,imposed \,\,by \,\,EEPROM \,\,read \,\,the \,\,SCLK \,\,period \,\,has \,\,to \,\,be \,\,increased \,\,to \,\,1\mu s \,\,(this \,\,limitation \,\,is \,\,imposed \,\,by \,\,EEPROM \,\,read \,\,the \,\,SCLK \,\,be \,\,increased \,\,to \,\,1\mu s \,\,(this \,\,limitation \,\,is \,\,imposed \,\,by \,\,EEPROM \,\,read \,\,the \,\,SCLK \,\,be \,\,increased \,\,to \,\,1\mu s \,\,(this \,\,limitation \,\,is \,\,imposed \,\,by \,\,EEPROM \,\,read \,\,the \,\,SCLK \,\,be \,\,increased \,\,to \,\,1\mu s \,\,(this \,\,limitation \,\,is \,\,imposed \,\,by \,\,EEPROM \,\,read \,\,the \,\,SCLK \,\,be \,\,increased \,\,to \,\,1\mu s \,\,(this \,\,limitation \,\,is \,\,imposed \,\,by \,\,EEPROM \,\,read \,\,the \,\,SCLK \,\,be \,\,increased \,\,to \,\,1\mu s \,\,(this \,\,limitation \,\,is \,\,imposed \,\,by \,\,EEPROM \,\,read \,\,the \,\,SCLK \,\,be \,\,increased \,\,to \,\,3\mu s \,\,(this \,\,limitation \,\,is \,\,imposed \,\,by \,\,EEPROM \,\,read \,\,the \,\,SCLK \,\,be \,\,increased \,\,to \,\,3\mu s \,\,(this \,\,s)$ access time)

 $<sup>2.</sup> T_{NCSL} = 300 \mu s min in Power mode 0.$ 



Figure 66: SPI General Timing

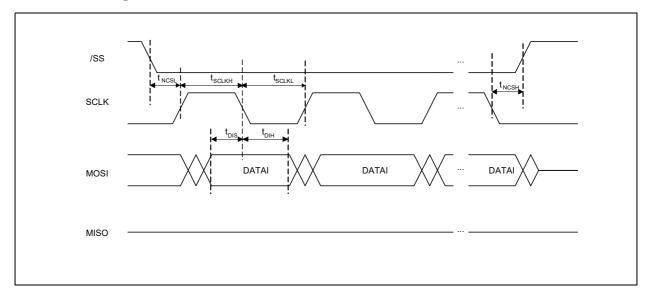
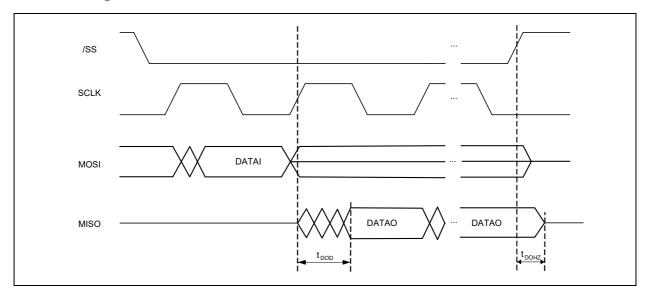


Figure 67: SPI Read Timing



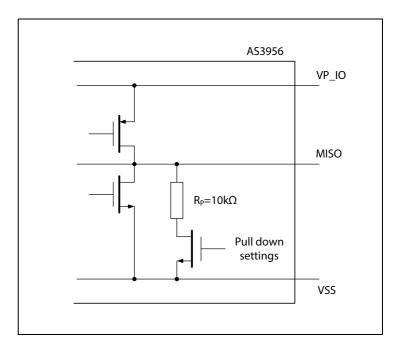
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## **SPI Electrical Connection**

A pull-down resistor can be connected by setting miso\_pd1 in IO Configuration Register.

Figure 68: SPI Electrical Connection



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### I<sup>2</sup>C Interface

Communication between AS3956 and microcontroller can be done via a I<sup>2</sup>C interface and an additional interrupt signal (pin IRQ). Please note a 100k ohm pull down resistor is recommended to be connected to the IRQ pin to prevent IRQ from floating when /SS is high. AS3956 acts an I<sup>2</sup>C slave device, and supports single master, multiple slave configurations. AS3956 I<sup>2</sup>C supports following modes: Standard-mode, Fast-mode, Fast-mode Plus. In addition to Schmitt triggers on all digital input lines a glitch suppression filter is implemented on the SCL and SDA input lines and suppresses glitches up to T<sub>qs i2c</sub> in length.

Figure 69: I<sup>2</sup>C and Interrupt Signals

Name	Signal	Signal Level	Description	
/SS	Digital Input with pull-up	CMOS	Should be set to low during I <sup>2</sup> C communication	
SDA	Digital Output	CMOS	Serial data output	
SCL	Digital Input	CMOS	Clock for serial communication	
IRQ	Digital Output	CMOS	Interrupt output pin (active high)	

During I<sup>2</sup>C communication, the signal /SS should be set to low. By setting the /SS to low, I<sup>2</sup>C interface is enabled. It is recommended to keep signal /SS high whenever the I<sup>2</sup>C interface is not used. The I<sup>2</sup>C bus is reset when /SS is high.

I<sup>2</sup>C interface supports the following modes:

- Internal registers read and write
- · EEPROM read and write
- · Buffer read and write
- Direct commands

Please note that the only I<sup>2</sup>C operations allowed, when logic and EEPROM are supplied from VP\_IO, are EEPROM and registers reading and writing (see also Power Management).

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### I<sup>2</sup>C Slave Address

The I<sup>2</sup>C slave address is composed of 7 bits where the first 4 MSBs are fixed and the last 3 LSBs are programmable.

Figure 70: I<sup>2</sup>C Slave Address

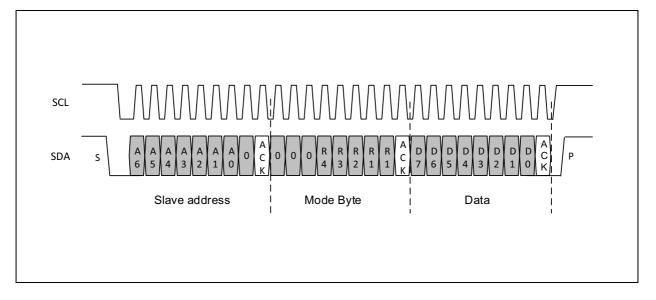
	В6	B5	B4	В3	B2	B1	ВО
I <sup>2</sup> C Slave Address	1	0	1	0	A2	A1	A0

The value of bits A2:A0 can be set in the Configuration Byte IC\_CFG0.

Writing Data to Addressable Registers (Register Write Mode)

Following figures show cases of writing a single byte and writing multiple bytes with auto-incrementing address. After the I<sup>2</sup>C slave address, the initial register address follows. Then one or more data bytes are transferred from the I<sup>2</sup>C, MSB first. The data byte is written in register on falling edge of its last clock.

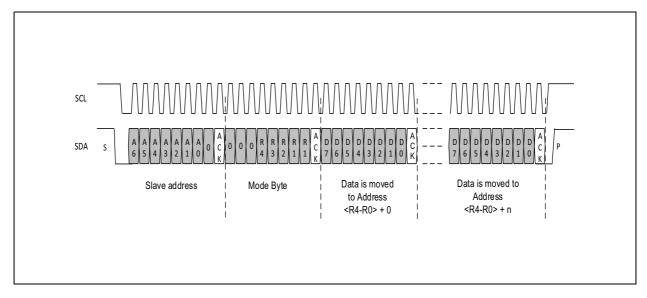
Figure 71: Writing a Single Register over I<sup>2</sup>C



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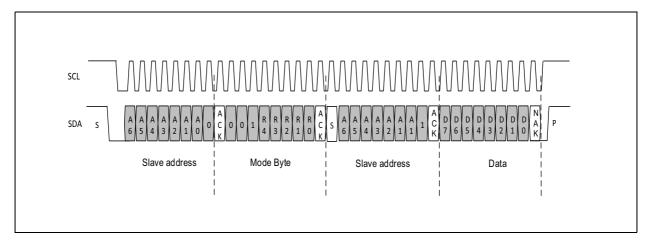
Figure 72:
Writing Register Data with Auto-Incrementing Address over I<sup>2</sup>C



Reading Data from Addressable Registers (Register Read Mode)

After the I<sup>2</sup>C slave address, the address of register to be read shall be provided, MSB first. Then one or more data bytes are transferred to SDA output, also MSB first. As in case of the write mode, also read mode supports auto-incrementing address. In case the register at the defined address does not exist, all 0 data is sent to SDA. In the following figure, an example for reading of single byte is given.

Figure 73: Reading a Single Register over I<sup>2</sup>C



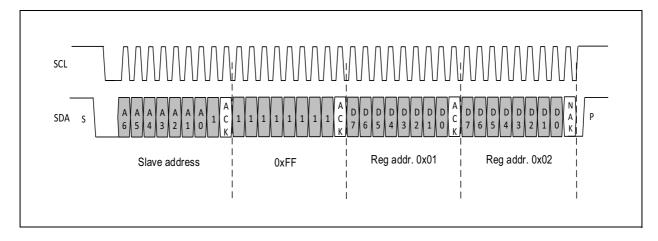
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#### Immediate Slave Read

All I<sup>2</sup>C sequences for AS3956 starts with slave address and read/write bit set to zero (write) so that MCU can send the command byte to the AS3956. A special case is where the MCU sets the read/write bit to one in the first byte. In this case the AS3956 will send back the content of registers starting from address 0x01. If the address is incremented beyond the address space of the registers, the AS3956 will transmit back zeros. The first returned byte by AS3956 is data value 0xFF.

Figure 74: Immediate Slave Read



### Writing and Reading EEPROM through I<sup>2</sup>C

EEPROM data can be read and written through I<sup>2</sup>C interface. Arbitration between EEPROM accesses via the RF and SPI/I<sup>2</sup>C interface are performed on a first-come-first-serve basis as described in Interface Arbitration.

## **Block Address Byte**

Both EEPROM Read and Write use Block Address byte to define the EEPROM block address to be accessed. Seven MSB bits of the Address Byte are used to define the address; while the last bit is don't-care (it is used to synchronize EEPROM access).

Figure 75: EEPROM Block Address Byte over I<sup>2</sup>C

	В7	В6	B5	B4	В3	B2	B1	В0
EEPROM Block Address	WA6	WA5	WA4	WA3	WA2	WA1	WA0	х

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#### **EEPROM Write**

In order to program an EEPROM block, seven bytes shall be sent (slave address, mode byte, block address byte and 4 bytes of data, all of them MSB first). Actual EEPROM programming is started with rising edge of ACK of the last byte. The EEPROM write is initiated after 4th data byte. All other bytes that might follow are rejected (a NAK on I<sup>2</sup>C line is returned).

Figure 76: Writing EEPROM Data with Auto-Incrementing Address over I<sup>2</sup>C

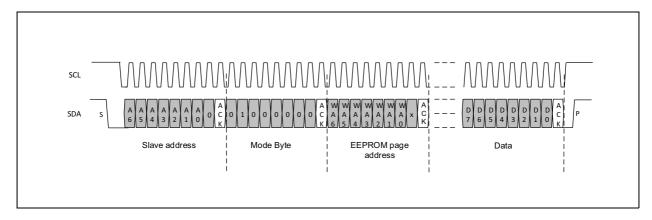


Figure 77: I<sup>2</sup>C Timing

Symbol	Parameter	Min	Тур	Max	Unit	Note			
	General Timing (VDD_IO= 3.3V, Temperature 25°C)								
f <sub>SCL_I2C</sub>	SCL clock frequency	100		1000	kHz				
T <sub>EW_I2C</sub>	EEPROM write timing. Rising edge of ACK of the last byte to interrupt io_eewr		8.3	9.5	ms				
T <sub>gs_i2c</sub>	Glitch suppression on SDA, SCL lines	30		48	ns				

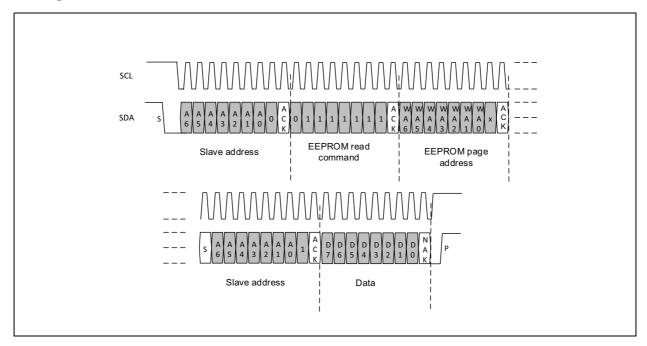
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#### **EEPROM Read**

In order to read data from EEPROM, first a slave address and mode byte is sent, followed by the block address byte (MSB first). Then one or more blocks of data with address auto-incrementing (packets of 4 bytes) are transferred via SDA line, also MSB first. SDA is sampled at the SCL falling edge. In case the block on defined address does not exist, all 0 data is sent via SDA line.

Figure 78: Reading a EEPROM Block over I<sup>2</sup>C

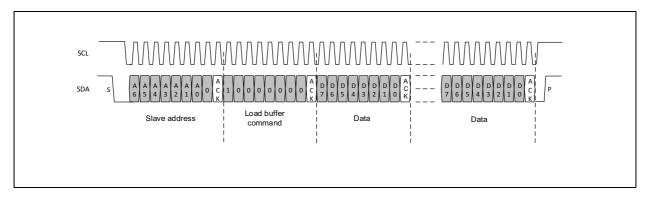


#### **Loading Transmission Data into Buffer**

Loading the transmitting data into the buffer is similar to writing data into an addressable register. Difference is that, in case of loading more bytes, all bytes go to the buffer. The command mode code 10b indicates buffer operations.

The following figure shows how to load the transmitting data into the buffer.

Figure 79: Loading Data into Buffer over I<sup>2</sup>C



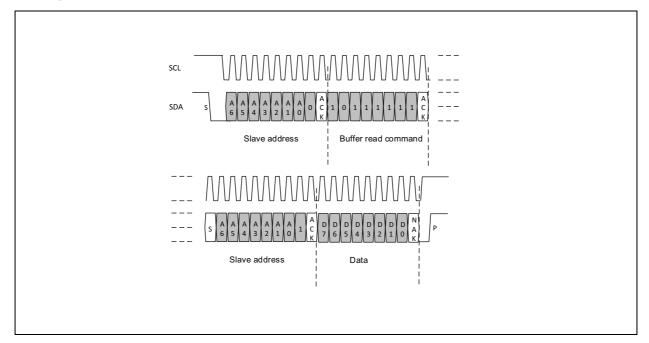
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## Reading Received Data from Buffer

Reading received data from the buffer is similar to reading data from an addressable register. Difference is that, in case of reading more bytes, they all come from the buffer. The command mode code 10b indicates buffer operations. In case of reading the received data from the buffer, all bits <C5 - C0> are set to 1.

Figure 80: Reading Data from Buffer over I<sup>2</sup>C



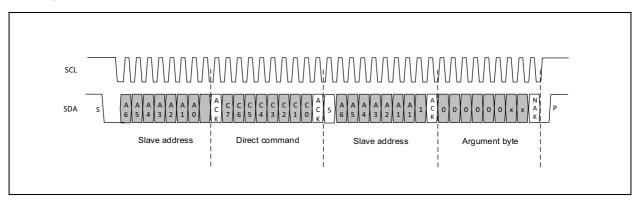
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#### **Direct Command Mode**

Direct Command Mode is comprised of one command byte and argument byte. The two msb's of command code 11b indicate Direct Command Mode. The following six bits define command code, sent MSB first. Last two bits in argument byte indicate success of the direct command. Value 01h of the argument byte indicates that command was accepted, while 02h indicates it was rejected due to internal access priorities. The argument byte does not provide information on timing of the command execution.

Figure 81: Sending a Direct Command over I<sup>2</sup>C



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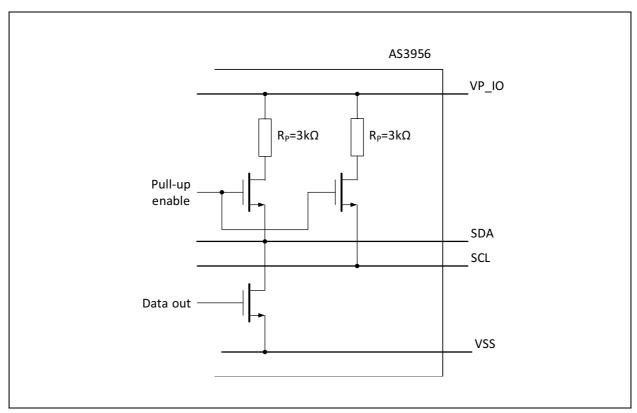
#### I<sup>2</sup>C Electrical Connection

The I<sup>2</sup>C bus can operate from a minimum of 100kHz up to 1MHz SCL clock speed. The I<sup>2</sup>C bus needs pull-up resistors on SDA and SCL lines in order to operate properly. AS3956 has internal pull-up resistors that can be used instead of external pull-ups. The intention of internal pull-up resistors is to simplify the design of the PCB and to decrease the number of necessary components on a PCB.

The configuration of the internal pull-up resistors is stored in configuration word 1 (FAB\_CFG2, bit 5) in EEPROM. This setting can be set only during the production. If this bit is not set, the internal pull-up resistors are disabled.

Note the SPI pull-down configuration bit miso\_pd1 in FAB\_CFG2 must also be set to 0.

Figure 82: I<sup>2</sup>C Interface with Built-In Pull-Up Resistors



Internal pull-up resistors are enabled only if proper configuration is written in the internal EEPROM configuration word. The configuration is read during the initialization of the chip when the interface and other configurations are set.

Note the pull-up resistors are applied to the SDA and SCL lines during chip initialization until the /SS line is taken low. After /SS is taken low, bit b5 of FAB\_CFG2 determines whether the pull-up resistor are connected or not.

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After first initialization the configuration of the EEPROM is read and the configuration of the internal pull-up resistors is stored in registers directly supplied by the VP\_IO. This means that if the chip is disabled by setting line /SS low the configuration will be kept. This means that after first initialization the internal pull-up resistors will be active even if the chip is set into stand-by mode using /SS line.

# Strong and Weak Pull-Up Behavior during Chip Initialization

When powered up by the VP\_IO without an RF field present, chip initialization takes place when the /SS pin is taken low. Between the time when power is applied to VP\_IO and /SS going low, strong pull-ups (3k ohm) are applied to the SDA/MISO and SCL/SCLK lines regardless of whether the chip is configured for SPI or I<sup>2</sup>C. Further during this period a weak pull (nominally 350k ohm) is connected to /SS. After /SS goes low the weak pull-up on /SS is removed and the strong pull-ups are configured according to FAB\_CFG2.

## Interrupt Interface Description

There are two interrupt registers implemented in AS3956 (Interrupt Register 0 and Interrupt Register 1).

When an interrupt condition is met, the source of interrupt bit is set in the interrupt register and the IRQ pin goes to high.

The microcontroller shall read the interrupt registers to distinguish between different interrupt sources. After an interrupt register is read, its content is reset to 0. IRQ pin goes to low after the interrupt bit(s), which caused its transition to high, has been read. Please note that there may be multiple interrupt register bits set in case the controller does not immediately read the Interrupt Registers after the IRQ signal was set and another event causing interrupt occurred.

The process of reading interrupt registers is composed of two phases. In the first phase, interrupts are pushed into internal buffer just before reading the first bit of the register. In the second phase the bits stored in the buffer are read out. The interrupts stored in each internal register are cleared and considered being read out at the rising edge of SCLK of the first interrupt bit for each interrupt register.

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#### **Buffer Interrupts and Buffer Status Register**

The AS3956 contains a 32 byte buffer. In case of transmission the Control logic shifts data which was previously loaded by the external controller to the Framing Block and further to the Transmitter. During reception, the demodulated data is stored in the buffer and the external controller can download received data.

Transmit and receive capability of the AS3956 is limited by the buffer size. The maximum message size that can be received or transmitted is 32 bytes. The mutual access to the buffer from NFC block and SPI / I<sup>2</sup>C block is not allowed. At the beginning of each reception the buffer is cleared automatically. Before the data is loaded into the buffer via SPI / I<sup>2</sup>C for transmission the MCU must take care of clearing the buffer.

Five interrupts that can be triggered during read or write of the buffer:

- When buffer overflow or underflow is detected an I\_bf\_err is triggered. The reason for the interrupt can be distinguished by reading the Buffer Status Register 1.
- Buffer overflow IRQ is not blocked, in case if more than 32 bytes are received from reader or written via SPI / I<sup>2</sup>C into buffer the buffer underflow IRQ is produced.
- When data is loaded via data RF an I\_rxs and I\_rxe are triggered
- When all data is transmitted an I\_txe is triggered
- When buffer is already busy due to another operation in progress and MCU tries to access the internal buffer an interrupt I\_acc\_err shall be triggered.

After data is received, the microcontroller shall check the amount of bytes actually received. This information is available in the Buffer Status Register 2, which displays number of bytes in the buffer not yet read out. Buffer Status Register 1 additionally contains a flag indicating buffer overflow.

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#### **EEPROM Read and Write**

The EEPROM can be accessed from SPI /  $I^2C$  interface or over RF field issuing NFC read and write commands. The EEPROM access is controlled by the internal EEPROM controller. Since the mutual access to the EEPROM is not possible AS3956 needs to arbitrate between MCU and NFC device in cases of mutual access. How this is handled it is defined according to arbit\_mod bit. EEPROM programing time is  $T_{EWS}$ . Please note that word data is sent MSB first which is opposite to the RFID EEPROM programming where LSB is sent first.

Three interrupts can be triggered during EEPROM read or write:

- When EEPROM programing is executed successfully an I\_io\_eewr interrupt is triggered.
- When EEPROM programming is terminated due to higher priority of the RF part, writing to a non-existent address or writing is not allowed an I\_eeac\_err interrupt is triggered.
- When EEPROM is busy and can't be accessed an I\_acc\_err interrupt is triggered

Please note it is recommended when reading or writing to EEPROM via SPI/I<sup>2</sup>C, the MCU should first check whether there is enough energy available, then switch to Power mode 3 and execute the SPI/I<sup>2</sup>C read or write and finally switch back to the original power mode if required. In Power mode 3 the internal supply is derived from VP\_IO and not the field. Switching to Power mode 3 will avoid that the supply voltage source for the internal chip supply might be changed during an EEPROM SPI/I<sup>2</sup>C read or write.

Also note that EEPROM does not contain any kind of anti-tearing mechanism that would allow detection of corrupted data

The valid range for the Block Address byte depends on the EEPROM size. For 4kbit EEPROM, the valid range for the Block Address byte is from 000\_0000b to 111\_1111b (EEPROM blocks from 00h to 7Fh).

### Data Buffer

Data in buffer is organized in bytes; each byte is terminated by a parity bit. Data bits in a byte are numbered from b1 to b8 where b1 is LSB bit, LSB is sent first.

Data sent over SPI / I<sup>2</sup>C is also organized in bytes, bits in a byte are marked D0 to D7, where D0 is LSB bit, MSB is sent first. During reception, the framing engine checks the parity bit and removes it from data frame, and only data bytes are put into buffer. During transmission, the process is reversed, only data bytes are put into buffer, while the framing engine adds the parity bits.

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The data bits b1 to b8 are mapped to buffer data bits D0 to D7, which means that the order of receiving/transmitting bits in a byte is reversed (the bytes are sent LSB first while the SPI /  $I^2C$  bytes are sent MSB first).

#### **Direct Commands**

The direct command consist of command byte and status byte returned by the AS3956 (the command sequence depends on the interface type). The command execution is initiated at the end of the command byte. The execution of the command is not cancelled if the command sequence is interrupted while reading status byte.

Figure 83: List of Direct Commands

Command Byte Value <hex></hex>	Command	Comments
C2	Set Default	Set AS3956 to default state
C4	Clear Buffer	Clears buffer and its error flags
C6	Restart Transceiver	Restarts transceiver communication logics
C7	Disable/Enable Transceiver	Toggles disable transceiver bit
C8	Transmit Buffer	Starts a transmit sequence of the buffer content
C9	Transmit ACK	Transmits NFC ACK reply
CA	Transmit NACK 0	Transmits NFC NAK reply with code 0h
СВ	Transmit NACK 1	Transmits NFC NAK reply with code 1h
CD	Transmit NACK 4	Transmits NFC NAK reply with code 4h
CC	Transmit NACK 5	Transmits NFC NAK reply with code 5h
D0	Go To Sleep	Puts a tag in SLEEP state
D1	Go To Sense	Puts a tag in SENSE state
D2	Go To Sense / Sleep	Puts a tag in SENSE or SLEEP state depending on the internal AS3956 state

#### Set Default

This direct command puts the AS3956 in the same state as power-up initialization except for I<sup>2</sup>C bit in register IC Status Display Register that defines the interface and IO Configuration Register, which are not cleared.

### Clear Buffer

Clears buffer, buffer overflow and underflow bits.

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#### Restart Transceiver

Resets protocol logic to its initial state except for the tag state. This interrupts all receptions and transmissions that are being processed at the time.

#### Disable/Enable Transceiver

This direct command toggles internal states which enables or disables the reception or transmission of the data. This command should be used when MCU wants to disable the interruption of EEPROM write/read over SPI/I<sup>2</sup>C by the received RF write/read command. This command shall not change the tag state. Please note that power-up and EEPROM arbitration interrupts are still produced when the transceiver is disabled. The transceiver state (ON/OFF) is ON after power -up of the chip, but after that the transceiver state can only be determined from the initial state (ON) and the number of Disable/Enable transceiver toggle commands that have been sent to the chip.

#### **Transmit Buffer**

This direct command trigger the transmission of data stored in the buffer over the RF link. Before issuing a Transmit command, the MCU shall send a Clear Buffer command, and write into the buffer the data to be transmitted by sending a Buffer Load command.

Execution of this direct command is only enabled when the AS3956 antenna coil is in a PCD field (VP INT is above HF PON threshold) and AS3956 Extended or Tunneling modes are enabled.

#### **Transmit ACK**

Transmit 4-bit ACK response.

#### Transmit NACK 0-5

Transmit 4-bit NACK response with different NACK codes.

#### Go To Sleep

Puts tag in SLEEP state. Execution of this direct command is only enabled when AS3956 antenna coil is in a NFC device field (VP\_ INT is above HF\_PON threshold).

#### Go To Sense

Puts tag in SENSE state. Execution of this direct command is only enabled when the AS3956 antenna coil is in a NFC device field (VP INT is above HF PON threshold).

#### Go To Sense / Sleep

Puts tag in SLEEP state depending on the internal state of the tag. Execution of this direct command is only enabled when AS3956 antenna coil is in a NFC device field (VP\_INT is above HF\_PON threshold).

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# **Register Description**

The 6-bit register addresses below are defined in hexadecimal notation. The possible address range is from 00h to 3Fh.

There are two types of registers implemented in AS3956: configuration registers and display registers. The configuration registers are used to configure AS3956. They can be written and read through SPI / I<sup>2</sup>C (RW). The display registers are read-only (RO); they contain information about AS3956 internal state, which can be accessed through SPI / I<sup>2</sup>C. Note that registers cannot be accessed over RF.

# **Registers Overview**

Figure 84: List of the SPI / I<sup>2</sup>C Internal Registers

Address [hex]	Content	Comment	Туре
00	IO Configuration Register		RW
01	IC Configuration Register 0	Default: IC_CFG0	RO/RW
02	IC Configuration Register 1	Default: IC_CFG1	RO/RW
03	IC Configuration Register 2	Default: IC_CFG2+ battery supply enable	RO/RW
04	RFID Status Display Register		RO
05	IC Status Display Register		RO
08	Mask Interrupt Register 0	Default: MIRQ_0	RW
09	Mask Interrupt Register 1	Default: MIRQ_1	RW
0A	Interrupt Register 0		RO
ОВ	Interrupt Register 1		RO
0C	Buffer Status Register 2		RO
0D	Buffer Status Register 1		RO
0E	Last NFC Address Access Register		RO
1C	Product type		RO
1D	Product subtype		RO
1E	Version Control – Major Revision		RO
1F	Version Control – Minor Revision		RO

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# **IO Configuration Register**

Figure 85: IO Configuration Register

	Address 00h: IO Configuration						
Bit	Name	Default	Function	Туре			
7	i2c_pu	0	1: Enable pull-ups for SDA and SCL when I <sup>2</sup> C is used	RW			
6	miso_pd1	0	1: Pull down on MISO when \SS is high	RW			
5	NA	0	Do not change from default	RW			
4							
3							
2							
1							
0							

#### Note(s):

1. Default value is loaded from EEPROM configuration word bits (FAB\_CFG2). This register values are stored in registers that are supplied always when there is VDD\_IO or RF present regardless to the BSS line status.

# **IC Configuration Registers**

# Figure 86: IC Configuration Register 0

Address 01h: IC Configuration 0						
Bit	Name	Default	Function	Type		
7	sInt_mod		1: Enable silent mode	RO		
6	slnt_vl<2>					
5	slnt_vl<1>		Silent mode voltage level (see Silent Mode)	RO/RW		
4	sInt_vI<0>	<b>.</b>				
3	arbit_mod	See note		RW		
2	i2c_addr3<2>					
1	i2c_addr2<1>		I <sup>2</sup> C slave address	RO		
0	i2c_addr1<0>					

#### Note(s):

1. Default value is loaded from EEPROM configuration block bits (IC\_CFG0).

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Figure 87: IC Configuration Register 1

Address 02h: IC Configuration 1						
Bit	Name	Default	Function	Type		
7	en_rx_crc		1: CRC stored in the buffer in the Tunneling mode	RO		
6	vreg<4>					
5	vreg<3>		Voltage level for voltage regulator VP_REG (see Energy Harvesting)	RW		
4	vreg<2>	See note				
3	vreg<1>	- See Hote				
2	vreg<0>					
1	rreg<1>		Output resistance value for voltage regulator VP_REG	RW		
0	rreg<0>		(see Energy Harvesting)	NVV		

#### Note(s):

1. Default value is loaded from EEPROM configuration block bits (IC\_CFG1).

# Figure 88:

**IC Configuration Register 2** 

Address 03h: IC Configuration 2						
Bit	Name	Default	Function	Туре		
7	rfcfg_en			RO		
6	tun_mod	See note		RW		
5	ext_mod		See Configuration Byte IC_CFG2 for full	RW		
4	nak_on_crc_parity	0		RO		
3	auth_set	See note	description	RO		
2	selr_b6_inv	0		RO		
1	powm<1>	Coomata		RW		
0	powm<0>	See note		RW		

## Note(s):

1. Default value is loaded from EEPROM configuration block bits (IC\_CFG2)

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# **Status Display Registers**

Figure 89: **RFID Status Display Register** 

Address 04h: RFID Status Display						
Bit	Name	Fun	Туре			
7	hf_pon	1: PICC AFE is active		RO		
6	state<3>	0000: POWER OFF	1111: SECTORX 2			
5	state<2>	0001: SENSE 0011: RESOLUTION	1110: SELECTEDX 1010: SENSEX L2	RO		
4	state<1>	0010: RESOLUTION_L2 0110: SELECTED	1011: SENSEX	NO		
3	state<0>	0111: SECTOR_2	1001: SLEEP			
2	state_notvalid	1: State update – indicates that the	RO			
1	rfu			RO		
0	rfu			RO		

Figure 90: **IC Status Display Register** 

Address 05h: IC Status Display						
Bit	Name	Default	Function	Туре		
7	ee2k	See note (1)		RO		
6	i2c	See Hote (1)		RO		
5	chip_kill_2	0	Signal depends on the CHIP_KILL value at initialization	RO		
4	chip_kill_1	0	Signal depends on the CHIP_KILL value at initialization	RO		
3	auth_locked	0	Signal depends on the AUTH_CNT value	RO		
2	rfu	0		RO		
1	rfu	0		RO		
0	rfu	0		RO		

### Note(s):

1. Default is set during production

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# **Interrupt Registers**

Figure 91: Mask Interrupt Register 0

Address 08h: Mask Interrupt 0 <sup>(1)</sup>						
Bit	Name	Default	Function	Туре		
7	M_init		Mask I_init IRQ	RW		
6	M_wu_a		Mask I_wu_a IRQ	RW		
5	M_slp	<u>.</u>	Mask I_slp IRQ	RW		
4	M_eew_rf	Coopeta (2)	Mask I_eew_rf IRQ	RW		
3	M_eer_rf	See note (2)	Mask I_eer_rf IRQ	RW		
2	M_rxe		Mask I_rxe IRQ	RW		
1	M_txe	•	Mask I_txe IRQ	RW		
0	M_xrf		Mask I_xrf IRQ	RW		

#### Note(s):

- 1. The mask bits only mask the triggering of the physical interrupt line. The interrupt bits in the Interrupt register still get set when the interrupt is masked.
- $2.\ Default\ values\ are\ loaded\ from\ EEPROM\ configuration\ block\ bits\ (MIRQ\_0).$

Figure 92: Mask Interrupt Register 1

Address 09h: Mask Interrupt 1 <sup>(1)</sup>						
Bit	Name	Default	Function	Туре		
7	M_rxs		Mask I_rxs IRQ	RW		
6	M_frm_err		Mask I_frm_err IRQ	RW		
5	M_par_err		Mask I_par_err IRQ	RW		
4	M_crc_err	Coopeta (2)	Mask I_crc_err IRQ	RW		
3	M_bf_err	See note (2)	Mask I_bf_err IRQ	RW		
2	M_io_eewr		Mask I_io_eewr IRQ	RW		
1	M_eeac_err		Mask I_eeac_err IRQ	RW		
0	M_acc_err		Mask I_acc_err IRQ	RW		

#### Note(s):

- 1. The mask bits only mask the triggering of the physical interrupt line. The interrupt bits in the Interrupt register still get set when the interrupt is masked.
- 2. Default values are loaded from EEPROM configuration block bits (MIRQ\_1).

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Figure 93: **Interrupt Register 0** 

	Address 0Ah: Interrupt Register 0						
Bit	Name	Function Typ					
7	l_init	Initialise IRQ. Interrupt is triggered at each power up (RF or battery), when chip is already powered and RF field appears and after Go To Sleep, Go To Sense, Go To Sense / Sleep and Set Defaultcommand	RO				
6	l_wu_a	Wake-up IRQ at entry in SELECTED state	RO				
5	l_slp	IRQ due to reception of SLP_REQ command	RO				
4	l_eew_rf	PCD has updated the content of the data area					
3	l_eer_rf	PCD has read the content of the data area	RO				
2	l_rxe	IRQ due to End of Receive. Applicable when receive frame is put in buffer	RO				
1	I_txe	IRQ due to End of Transmission. Applicable when data from buffer is sent	RO				
0	l_xrf	Exit RF field IRQ	RO				

#### Note(s):

Figure 94: **Interrupt Register 1** 

Address 0Bh: Interrupt Register 1					
Bit	Name	Name Function			
7	l_rxs	IRQ due to Start of Receive. Applicable when receive frame is put in buffer	RO		
6	l_frm_err	Lower layer error (broken byte, wrong bit coding sequence) / In case of error the receive data is still put in buffer, error IRQ is additionally sent	RO		
5	l_par_err	Parity error / In case of error the receive data is still put in buffer, error IRQ is additionally sent	RO		
4	l_crc_err	CRC error / In case of CRC error the receive data is still put in buffer, error IRQ is additionally sent			
3	I_bf_err	Buffer error (overflow/underflow). See Buffer Status Register 2	RO		

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<sup>1.</sup> Power-up and Set Default command set the content of this register to 0. After Interrupt Register has been read, its content is set again to 0.



	Address 0Bh: Interrupt Register 1					
Bit	Name	Туре				
2	l_io_eewr	IRQ due to successful termination of EEPROM programming. In case EEPROM write command was sent through SPI / I <sup>2</sup> C	RO			
1	l_eeac_err	IRQ due to EEPROM write on write protected block or write to non-existing address	RO			
0	l_acc_err	IRQ due to interruption of SPI / I <sup>2</sup> C operation on buffer, EEPROM or registers due to access control	RO			

#### Note(s):

1. Power-up and Set Default command reset the content of this register to 0. After Interrupt Register has been read, its content is set again to 0.

# **Buffer Registers**

Figure 95: Buffer Status Register 2

Address 0Ch: Buffer Status Register 2				
Bit	Name	Function	Type	
7	buf_len_invalid	Buffer content is being changed – data length not valid	RO	
6	rfu		RO	
5	buf_len<5>			
4	buf_len<4>			
3	buf_len<3>	Number of data bytes (binary coded) in the buffer received from the reader in tunneling or extended mode and not yet read out	RO	
2	buf_len<2>	via SPI / I <sup>2</sup> C. Valid range is from 000000b to 100000b – 000000b means that there are no data bytes to be read out	, KO	
1	buf_len<1>	,		
0	buf_len<0>			

# Note(s):

1. Power-up and commands Set Default, Clear Buffer and Go To Idle/Halt reset the content of this register to 0.

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# Figure 96: Buffer Status Register 1

	Address 0Dh: Buffer Status Register 1				
Bit	Name	Function	Type		
7	rfu		RO		
6	rfu		RO		
5	rf_busy	Extended mode buffer status flags (see Extended Mode);	RO		
4	rf_data_rdy	io_busy flag is omitted since in this it is always zero when this	RO		
3	io_data_rdy	byte is read out	RO		
2	rfu		RO		
1	buf_unf	Buffer underflow. Set when read more bytes then actual content of buffer	RO		
0	buf_ovr	Buffer overflow. Set when written more bytes then actual content of buffer	RO		

#### Note(s):

1. Power-up and commands Set Default, Clear Buffer and Go To Idle/Halt reset the content of this register to 0.

# **NFC Last Address Register**

Figure 97: Last NFC Address Access Register

Address 0Eh: Last NFC Address Access								
Bit	Name	Function	Туре					
7	last_addr<7>							
6	last_addr<6>							
5	last_addr<5>	Contains last address accessed by reader. Updated on internal						
4	last_addr<4>	EEPROM access over RF. The address is 8 bit long and contains also access attempts that are higher than the EEPROM address space. Value FFh indicates that the value is being updated and is not valid.						
3	last_addr<3>							
2	last_addr<2>							
1	last_addr<1>							
0	last_addr<0>							

#### Note(s):

 $1. \ Power-up \ and \ commands \ Set \ Default \ and \ Clear \ Buffer \ reset \ the \ content \ of \ this \ register \ to \ 0.$ 

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# **Version Control Register**

Figure 98: Version Control – Major Revision

	Address 1Eh: Version Control – Major Revision						
Bit	Name	Default	Function	Туре			
7	maj7	0					
6	maj6	0					
5	maj5	0					
4	maj4	0	Major varsion rovision	PO			
3	maj3	0	Major version revision RO				
2	maj2	0					
1	maj1	0					
0	maj0	1					

Figure 99: Version Control – Minor Revision

Address 1Fh: Version Control – Minor Revision						
Bit	Name Default		Function	Type		
7	min7	0				
6	min6	0				
5	min5	0				
4	min4	0	Minor varsion rovision	RO		
3	min3	0	Minor version revision RC			
2	min2	0				
1	min1	0				
0	min0	0				

#### Note(s):

1. Default values are loaded from EEPROM configuration block bits (Configuration Bytes MIRQ\_0 and MIRQ\_1)

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# **Application Information**

This section describes some general use cases of AS3956 in combination with a microcontroller. The examples are shown for explanatory purposes of specific AS3956 features. Detailed descriptions of specific implementations are subject of dedicated Application Notes.

# Writing a NDEF Message into AS3956 Memory

AS3956 is an NFC Forum Type 2 Tag Platform and as such its memory has to have the layout defined in NFC Forum Type 2 Tag Operation Specification. In a Type 2 Tag platform data is stored in memory in the form of TLV blocks. A TLV block has three fields: T field - tag field, L field - length field and V field – value field.

- T field indicates the type of the TLV block and is one byte long.
- L field gives the size in bytes of the value field. It's 1 or 3 bytes long depending on the size of the value filed. When the size of the value field is between 0 and 254 bytes, the L field is one byte long and has a value between 00h and FEh. For sizes of the value field between 255 and 65535 bytes, the L field is 3 bytes long. First byte is FFh indicating that the size will be provided by the following two bytes that can have values between 00FFh and FFFEh.
- V field holds the bytes of the data carried by the TLV block. When the L field is zero or not present, the V field is omitted.

For NDEF messages the TLV block has a T field value of 03h and the message is stored inside the V field. The NDEF Message TLV should always be present in a T2T platform and at a minimum it is an empty NDEF Message TLV, which is defined as an NDEF Message TLV with L field equal 00h and no V field. For the NDEF message format refer to NFC Data Exchange Format Technical Specification.

Two more TLV types can exist in the memory, these are Lock Control TLV and Memory Control TLV. When they are present inside the memory, the NDEF Message TLV should be placed after them.

Another structure that has to be present in the memory of T2T platform is the Capability Container (CC). CC contains NFC Forum management data. It is comprised of 4 bytes and always resides at block number 03h of the memory.

The AS3956 comes with programmed CC (refer to Capability Container in the section Memory Organization of this datasheet), no Lock Control TLV and no Memory Control TLV. The NDEF Message TLV then can be placed already at the beginning of the data area of the memory - block 04h.

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Following is an example of an NDEF message with one Well Known URL record, which carries the http://www.ams.com URL:

- In the NDEF message format, the URL above will be represented by the bytes:
   [D1 01 08 55 01 61 6D 73 2E 63 6F 6D]h
- The NDEF Message TLV will have the content: [03 0C D1 01 08 55 01 61 6D 73 2E 63 6F 6D]h; first byte is 03h T field value, indicating this is an NDEF Message TLV, second byte is 0Ch saying the V field is 12 bytes long, the following 12 bytes are the V field holding the NDEF message.

The NDEF message TLV given above will fully occupy the first 3 blocks of the data area and the first two bytes of the 4th block of the data area (each memory block is 4 bytes long).

# Reading/Writing with an NFC Device

NFC devices use the T2T WRITE command to write data into a T2T platform. The T2T WRITE command consists of 6 bytes, 1st byte is the command code – A2h, 2nd byte is the block number where data is to be written and the remaining 4 bytes are the data content. When the execution of the command is successful, the tag will return an ACK response – A0h. In case of failure, a NACK code will be returned (see Error Handling section of this datasheet for NACK codes). If a write EEPROM command is the very last command to be sent from an NFC device then it is good practice to read back the data sent in the last write command. This is because EEPROM writing takes longer to execute. A successful read back will confirm the RF field and hence power was maintained during the EEPROM write and that the write was successful.

The T2T READ command consists of 2 bytes, first byte is the command code and is equal to 30h, second byte is the first block number from which data will be returned. The response, when successful, will return 4 blocks of data, each block is 4 bytes long, so 16 bytes of data. In case of error, one byte NACK response will be returned (see Error Handlingsection of AS3956 datasheet for NACK codes).

AS3956 has to be configured in Extended or Normal mode in order for an NFC device to write/read NDEF data from the EEPROM of the tag.

An NFC device has to send 4 write commands to the tag to write the NDEF Message TLV bytes [03 0C D1 01 08 55 01 61 6D 73 2E 63 6F 6D]hex defined in the section above into blocks 04h-07h:

- 1. [A2 04 03 0C D1 01]hex
- 2. [A2 05 08 55 01 61]hex
- 3. [A2 06 6D 73 2E 63]hex
- 4. [A2 07 6F 6D 00 00]hex

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The same NDEF Message TLV bytes can be obtained with a single READ command, as the TLV occupies only 4 blocks and the READ command returns 16 bytes. In case of longer NDEF messages of course several READs are necessary until the complete message has been read out.

#### Reading/Writing Through SPI / I<sup>2</sup>C

An MCU can write the NDEF Message TLV bytes [03 0C D1 01 08 55 01 61 6D 73 2E 63 6F 6D]hex into blocks 04h-07h by sending the following 4 bytes sequences through SPI or I<sup>2</sup>C (as described in the Wired Interfaces section of this datasheet):

#### Writing:

- 1. [40 08 03 0C D1 01]hex
- 2. [40 0A 08 55 01 61]hex
- 3. [40 0C 6D 73 2E 63]hex
- 4. [40 0E 6F 6D 00 00]hex

To read the same data bytes written in blocks 04h - 07h, the MCU should send the bytes sequences below (2 clock cycles for MODE and address and 4 additional clock cycles to read the data sent from AS3956, refer to the Wired Interfaces section of this datasheet):

- 1. [7F 08 00 00 00 00]hex
- 2. [7F 0A 00 00 00 00]hex
- 3. [7F 0C 00 00 00 00]hex
- 4. [7F 0E 00 00 00 00]hex

# Using Extended Mode to Switch AS3956 into Tunneling Mode

An NFC device can force the AS3956 in Tunneling mode by sending a command via Extended to the MCU to switch the AS3956 operating mode from Extended to Tunneling (refer to Extended mode section of this datasheet for implementation details). If the MCU should emulate a T4T after the switch, AS3956 should be sent to SENSE state by the MCU with the direct command "Go To Sense" (command code D1h) and the NFC device should do a new anti-collision round for proper T4T activation.

# Using Tunneling Mode to Emulate a NFC Type 4 Tag

For T4T emulation the Tunneling mode has to be enabled by setting the tun\_mod bit of IC\_CFG2 to 1 and the SELR to 0x20. With this configuration, once AS3956 has passed anti-collision and entered SELECTED state, all frames coming from the NFC interface will be pushed to the BUFFER. That means also the SENS\_REQ, ALL\_REQ, SSD\_REQ, SEL\_REQ and SLP\_REQ will not be executed by the AS3956, so MCU must send the tag to SLEEP

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state on SLP\_REQ (with direct command "Go To Sleep") and to SENSE state (with direct command "Go To Sense") on any of the other commands listed above.

The ISO14443A-4 command RATS should also be handled by the MCU. RATS is sent by an NFC device to activate ISO14443A-4, on top of which is T4T platform is implemented.

#### References

- [AN02] Mandatory Application Note AN02: Dual Interface Data Integrity.
- [EMVCO-1] EMVCo Type Approval Contactless Terminal Level 1 – PCD Digital Test Bench & Test Cases, version 2.3.1a, January 2013
- [ISO14443-3] ISO/IEC 14443-3:2011(E), Identification cards Contactless integrated circuit cards Proximity cards Part 3: Initialization and anticollision
- [ISO14443-4] ISO/IEC 14443-4:2008(E), Identification cards Contactless integrated circuit(s) cards Proximity cards Part 4: Transmission protocol
- [ISO18092] ISO/IEC 18092:2013 Information technology — Telecommunications and information exchange between systems — Near Field Communication — Interface and Protocol (NFCIP-1)
- [ISO7816-3] ISO/IEC 7816-3:2006, Identification cards Integrated circuit cards Part 3: Cards with contacts Electrical interface and transmission protocols
- [ISO7816-4] ISO/IEC 7816-4:2005, Identification cards Integrated circuit cards Part 4: Organization, security and commands for interchange
- [ISO7816-6] ISO/IEC 7816-6:2004, Identification cards Integrated circuit cards — Part 6: Interindustry data elements for interchange
- [NFC Analog] NFC Analog Specification NFC Forum, 11.07.2011, Version 1.0
- [NFC Digital] NFC Digital Protocol NFC Forum, 17.11.2010, Version 1.0
- [NDEF] NFC Data Exchange Format (NDEF), Technical Specification NFC Forum, 24.07.2006, Version 1.0
- [PHDC] Personal Health Device Communication), Technical Specification — NFC Forum, 27.02.2013, Version 1.0
- [T2T] Tag 2 Type Operation, Technical Specification NFC Forum, 31.05.2011, Version 1.1
- [T4T] Tag 4 Type Operation, Technical Specification NFC Forum, 28.06.2011, Version 2.0

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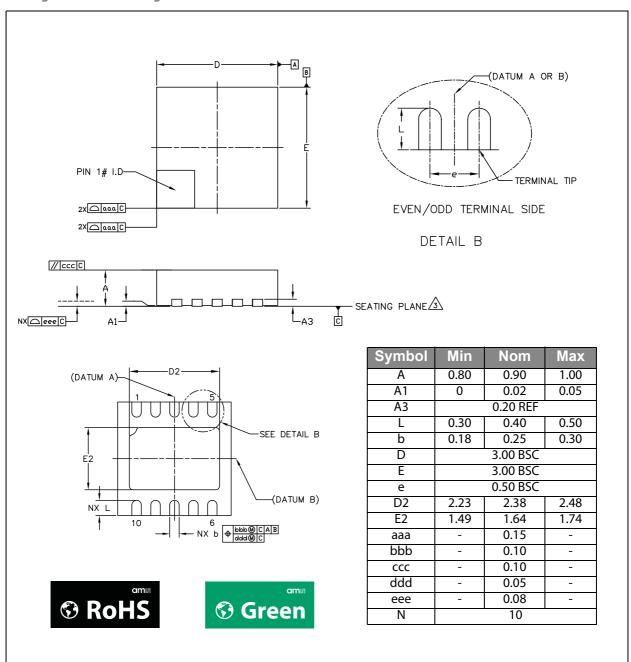
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# **Package Drawings & Markings**

Figure 100:
Package Outline Drawings MLPD



#### Note(s):

- 1. Dimensioning and tolerancing conform to ASME Y14.5M-1994.
- 2. All dimensions are in millimeters. Angles are in degrees.
- 3. Coplanarity applies to the exposed heat slug as well as the terminal.
- 4. Radius on terminal is optional.
- 5. N is the total number of terminals.

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Figure 101: Package Marking MLPD (I<sup>2</sup>C)

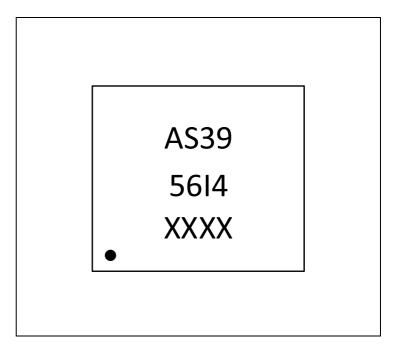


Figure 102: Package Marking MLPD (SPI)

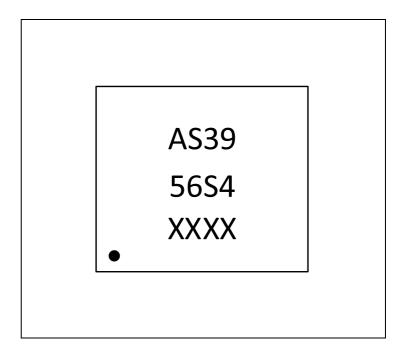
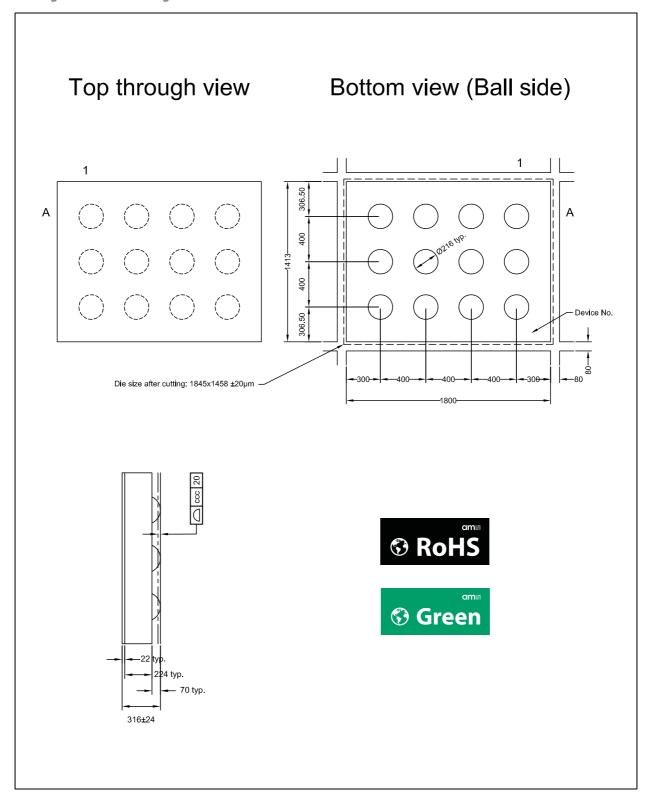


Figure 103: Package Code MLPD

XXXX	
Tracecode	



Figure 104: Package Outline Drawings Thin WL-CSP



#### Note(s):

- 1. Pin1 = A1.
- 2. ccc coplanarity.
- 3. All dimensions are in  $\mu\text{m}.$
- 4. This applies to ATWT and ATWM ordering codes.

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Figure 105: Package Marking WL-CSP

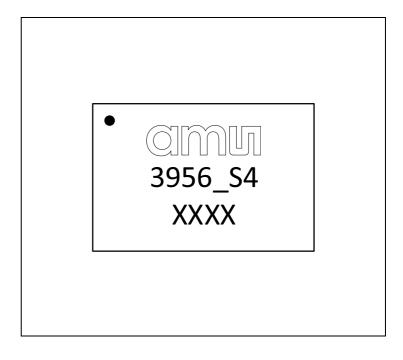


Figure 106: Package Code WL-CSP

XXXX	
Tracecode	

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# **Ordering & Contact Information**

Figure 107:
Ordering Information

Ordering Code	Package	Marking	Delivery Form	Delivery Quantity	Configuration
AS3956-ATDM-S4	MLPD	AS3956S4	Mini Reel	500 pcs/reel	SPI – Pull-down disabled
AS3956-ATDT-S4	MLPD	AS3956S4	Tape & Reel	10000 pcs/reel	SPI – Pull-down disabled
AS3956-ATDM-I4	MLPD	AS3956I4	Mini Reel	500 pcs/reel	I <sup>2</sup> C – Internal pull-up enabled
AS3956-ATDT-I4	MLPD	AS3956I4	Tape & Reel	10000 pcs/reel	I <sup>2</sup> C – Internal pull-up enabled
AS3956-ATDM-I3	MLPD	AS3956I3	Mini Reel	500 pcs/reel	I <sup>2</sup> C – Internal pull-up disabled
AS3956-ATDT-I3	MLPD	AS3956I3	Tape & Reel	10000 pcs/reel	I <sup>2</sup> C – Internal pull-up disabled
AS3956-ATWM-S4	Thin WL-CSP	3956_S4	Mini Reel	500 pcs/reel	SPI– Pull-down disabled
AS3956-ATWT-S4	Thin WL-CSP	3956_S4	Tape & Reel	12000 pcs/reel	SPI– Pull-down disabled
AS3956-ATWM-I4	Thin WL-CSP	3956_I4	Mini Reel	500 pcs/reel	I <sup>2</sup> C – Internal pull-up enabled
AS3956-ATWT-I4	Thin WL-CSP	3956_I4	Tape & Reel	12000 pcs/reel	I <sup>2</sup> C – Internal pull-up enabled
AS3956-ATWM-I3	Thin WL-CSP	3956_I3	Mini Reel	500 pcs/reel	I <sup>2</sup> C – Internal pull-up disabled
AS3956-ATWT-I3	Thin WL-CSP	3956_l3	Tape & Reel	12000 pcs/reel	I <sup>2</sup> C – Internal pull-up disabled

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# **Document Status**

Document Status	Product Status	Definition
Product Preview	Pre-Development	Information in this datasheet is based on product ideas in the planning phase of development. All specifications are design goals without any warranty and are subject to change without notice
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Updated Figure 1	2
Updated Figure 7 and added note	10
Updated Figure 10 and note under it	11
Updated text under Analog Frontend (AFE)	14
Updated text under Power Management	15
Updated text under Power Mode 0	15
Removed Figure in section Power Mode 0	15
Removed Power Mode 1 and Power Mode 2	16
Updated text under Power Mode 3	16
Updated Figure 14	17
Updated Energy Harvesting	18
Removed text under Figure 15	18
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Updated Figure 81	77
Updated text under EEPROM Read and Write	81
Updated text under Disable/Enable Transceiver	83
Updated heading to "Reading/Writing with an NFC Device" and text under it	94
Updated References	96
Updated Figure 107	101
Added and updated Appendix-Errata Notes	107

# Note(s):

- 1. Page and figure numbers for the previous version may differ from page and figure numbers in the current revision.
- $2. \, Correction \, of \, typographical \, errors \, is \, not \, explicitly \, mentioned.$

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# **Appendix - Errata Notes**

## **Deviation 1**

If both SDA and SCL lines go low possibly due to a glitch or during power up sequence then the next I<sup>2</sup>C command may be NACK'd

## **Description:**

When the I<sup>2</sup>C bus is idle, both SDA and SCL signals should be logic high. In the unusual case, both SDA and SCL signals go low possibly due to a glitch or during a power up sequence, then the next I<sup>2</sup>C command may be NACK'd.

#### **Workaround:**

If a NACK is returned by the I<sup>2</sup>C, please resend the I<sup>2</sup>C command.

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